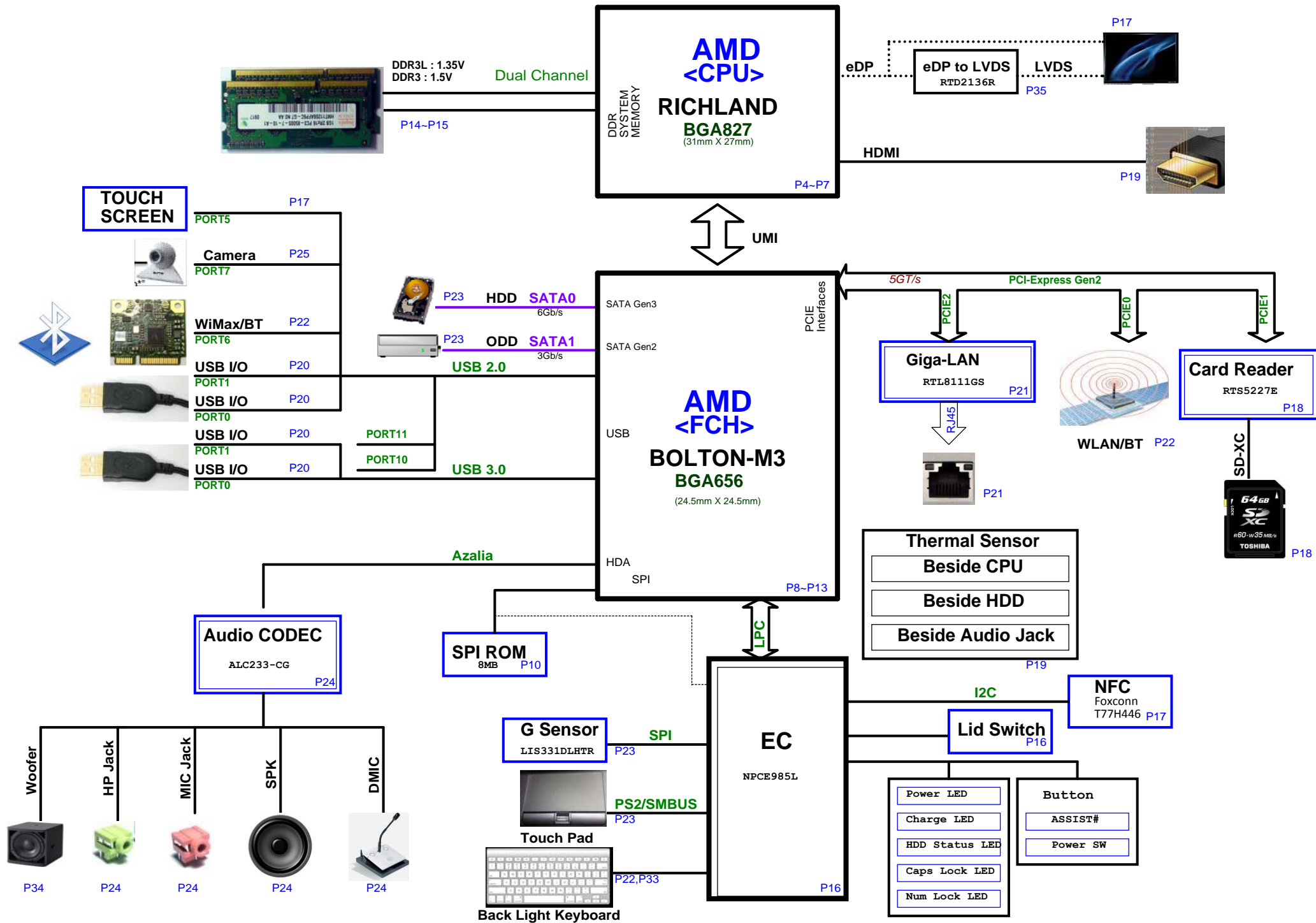


Page	Title of schematic page	Rev.	Date
01	Page List	1A	
02	Block Diagram	1A	
03	Change List	1A	
04	FP2 1/4 (PEG&UMI)	1A	
05	FP2 2/4 (DDR3 I/F)	1A	
06	FP2 3/4 (DP/MISC)	1A	
07	FP2 4/4 (POWER/GND)	1A	
08	FCH 1/6 (GPIO/USB/AZ)	1A	
09	FCH 2/6 (UMI/PCIE/PCI/CLK)	1A	
10	FCH 3/6 (SATA/VGA/SPI)	1A	
11	FCH 4/6 (POWER)	1A	
12	FCH 5/6 (Strap)	1A	
13	FCH 6/6 (GND)	1A	
14	DDR3 DIMM-0-STD	1A	
15	DDR3 DIMM-1-STD	1A	
16	WPCE985L & FLASH	1A	
17	LVDS\TS\NFC	1A	
18	CARD READER (RTS5209)	1A	
19	HDMI/THERMAL	1A	
20	USB	1A	
21	LAN (RTL8111GS)	1A	
22	WLAN/KB-BL	1A	
23	HDD/ODD/G-SENSOR/TP/FAN	1A	
24	Audio ALC233-CG	1A	
25	LED/PS/DMIC\Camera	1A	
26	POWER +VCC_CORE (ISL62771)	1A	
27	POWER 3VPCU&RVCC5 (TPS51427)	1A	
28	POWER 1.35VSUS/VTT_MEM	1A	
29	POWER +1.1V (G5602R41U) -5A	1A	
30	POWER VCC1.2/VCC2.5/Thermal	1A	
31	POWER (BAT IN / ADA IN/ UL)	1A	
32	POWER CHARGER (ISL88731C)	1A	
33	HOLE/EMI/KB	1A	
34	eDP to LVDS	1A	
35	IO PORT LIST	1A	

* : No mount
I@ : For native eDP output
D@ : For eDP to LVDS output



Change List

MB_SCH_DVT_001

P21 Reserve U30,LR12,LR13,LC21

Reason : For LAN S5 wake up won't be supported.
Possible Risk: No.

MB_SCH_DVT_002

P25 Chang R198 and R309 resistor

Reason : Modify circuit for LED Light

Possible Risk: No.

MB_SCH_DVT_003

P22 Delete R333 0ohm and add F9(0.35A) fuse

P22 Delete R468[100K],Q33[2N7002]

Reason : Modify circuit for KB BL protection.

Possible Risk: No.

MB_SCH_DVT_004

P9 Change part of Crystal Y1 32.768K.

Reason : Original part is EOD.

Possible Risk: No.

MB_SCH_DVT_005

P8 Modify circuit for NFC function.

Change R865,R866 to R861,R864.

change NFC_EN from GPIO166 to GEVENT22#.

Reason : To enable NFC function.

Possible Risk: No.

```
MB_SCH_DVT_006
P16 Reserve diode KD4 for EC_PWRBTN#.
P22 Reserve diode D12 for WLAN_RF_ON.
Reason :For cost down.
Possible Risk: No.
```

```
MB_SCH_DVT_007
P20 Add choke for USB ports.
P25 Add choke for Camera USB interface.
Reason :EMI issue.
Possible Risk: No.
```

MB_SCH_DVT_008

P7,P11 Change capacitors 22U X5R 0805 to 22U X5R 0603.

Reason :To enlarge the distance between Cap. and Keyboard.

Possible Risk: No.

MB_SCH_DVT_009

P33 Change FCH NUT shape.

Reason :To fit screw's size.

Possible Risk: No.

```
MB_SCH_DVT_010
P16 Add KR42 10K ohm.
Reason :To fit LVDS panel power sequence.
Possible Risk: No.
```

```
MB_SCH_DVT_011
P8 Add SMBUS path from FCH to RTD2136R.
Reason :Reserve the way to flash RTD2136R eFuse.
Possible Risk: No.
```

MB_SCH_DVT_012

P9,P21 Change Capacitors for XTAL Y2, LY1.

Reason :For more precisely frequency of XTAL.

Possible Risk: No.

MB_SCH_DVT_013

P19 Change Resistor of HDMI signals resistors.

Reason :For better HDMI signal quality.

Possible Risk: No.

MB_SCH_PVT_001-0606

P17 Change LVDS connector.

Reason : For factory's strong request.

Possible Risk: No

MB_SCH_PVT_002-0606

P23 Remove R303, R304.

Reason : To remove SMBUS interface of TP.

Possible Risk: No

MB_SCH_PVT_003-0606

P6 Add R790, C547, C548 for APU_PWRGD, APU_RST#

Reason : To reduce noise.

Possible Risk: No

MB_SCH_PVT_004-0610

P8 Add R792, R793 and NFC-IRQ_FCH_1

Reason : Change NFC IRQ to GEVENT18 and reserve GEVENT5.
Possible Risk: No

MB_SCH_PVT_005-0610
P20 Add D23-D30
P24 Add AD8-AD13
Reason : For ESD protection.
Possible Risk: No

MB_SCH_PVT_006-0611

P33 Add RP1-RP7

Reason : For ESD protection.

Possible Risk: No

```
MB_SCH_PVT_007-0611
P33 Add D35,R775,C549 but reserved.
Reason : reserved for NFC power sequence.
Possible Risk: No
```

MB_SCH_PVT_008-0614

P19 Change value of RI02,RI79.

Reason : For thermal shutdown protection by Thermal RD's suggestion.

Possible Risk: No

POWER

2A-P1
Change PC580 and PC599 from 0.047u to 0.068 for fine tune IC response

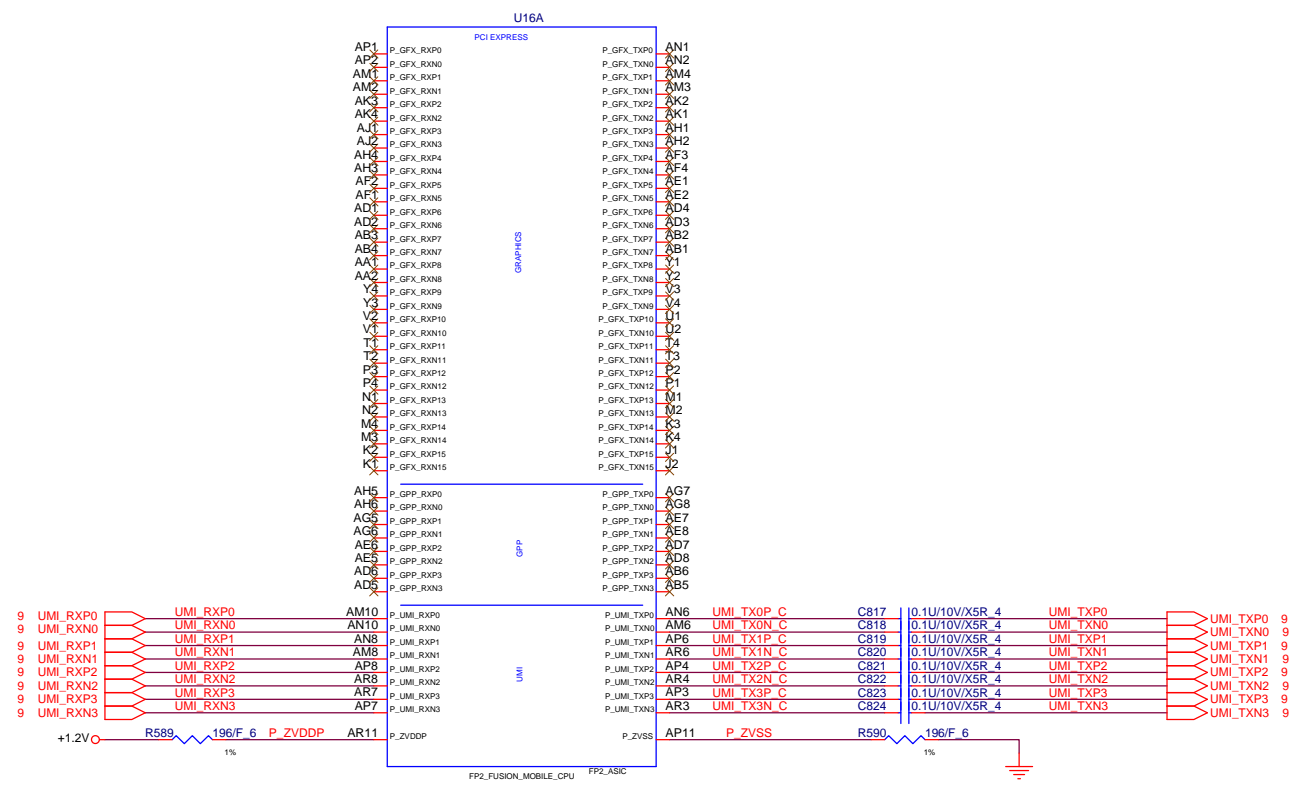
2A-P2
add PC617, PC618, PC619, PC620 for meet AMD SPEC of ripple

2A-P3
change PR58 from 255k to 196k for fine tune OCP

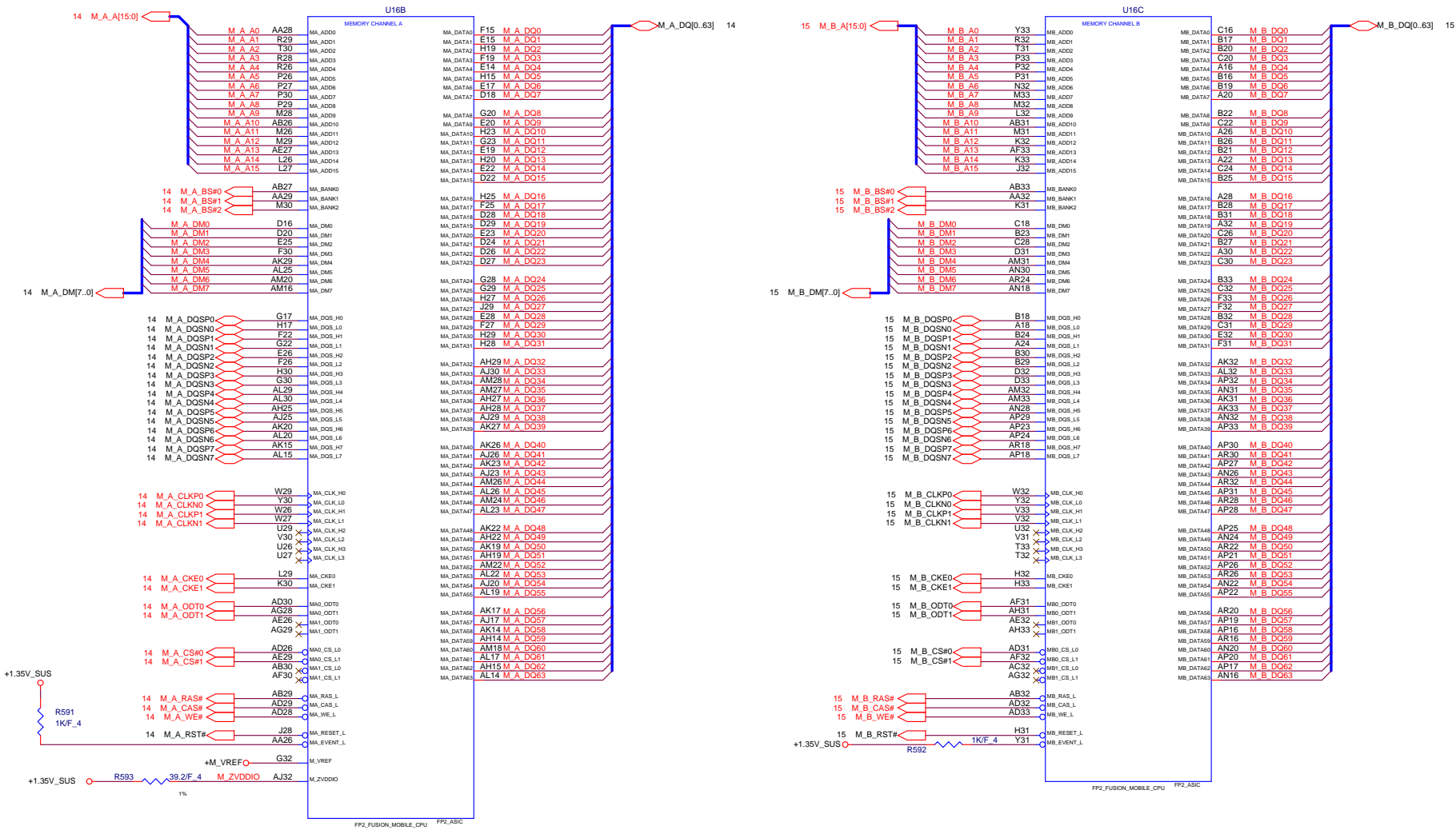
2A-P4
change from 3.75k to 3K for fine tune OCP

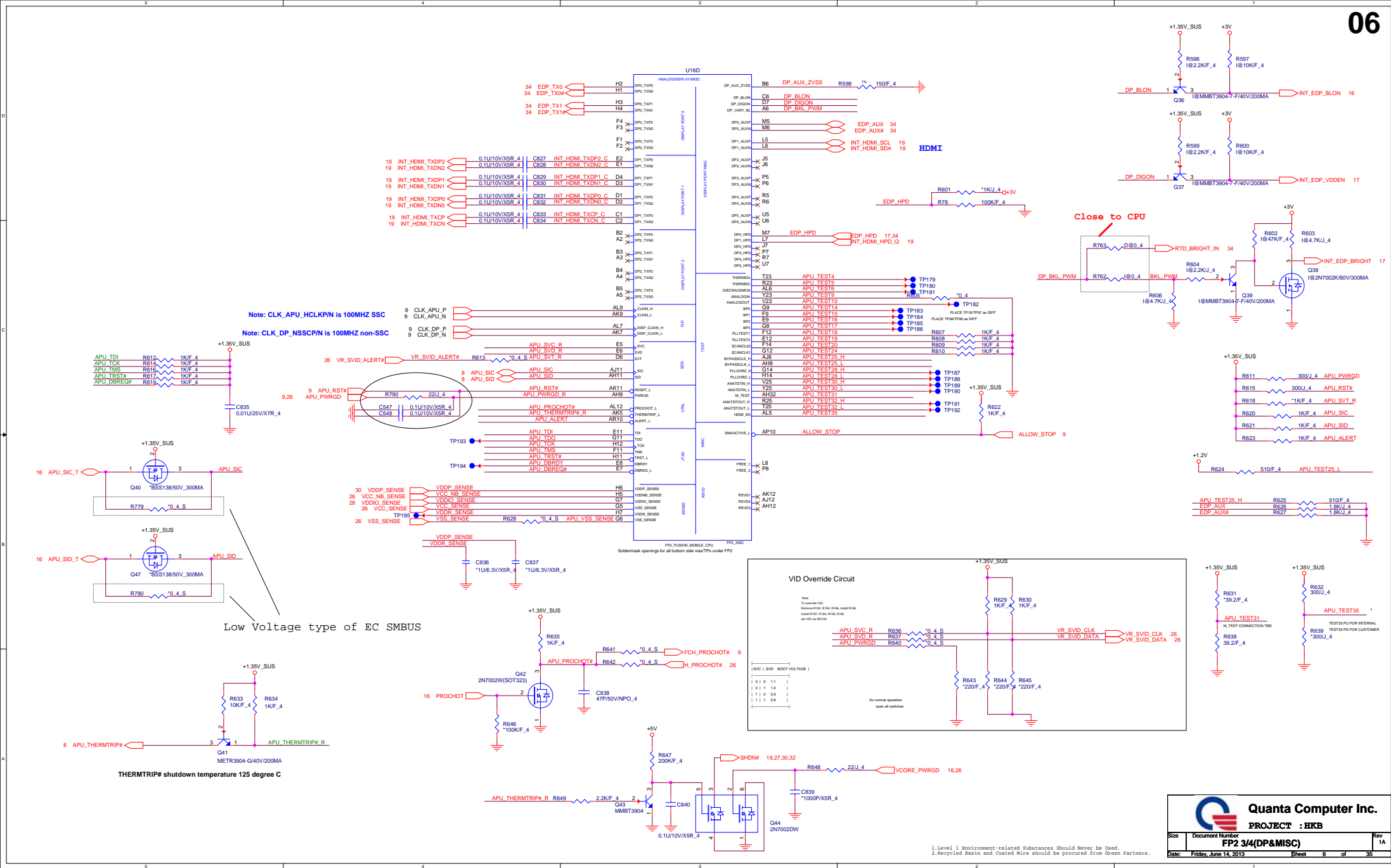
3A-P1
change to origin one for better OVP accuracy

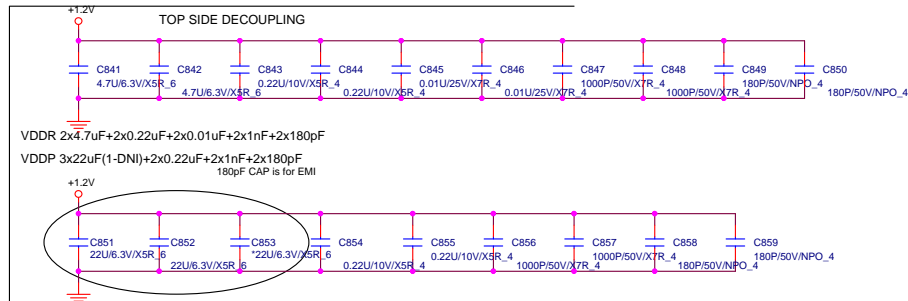
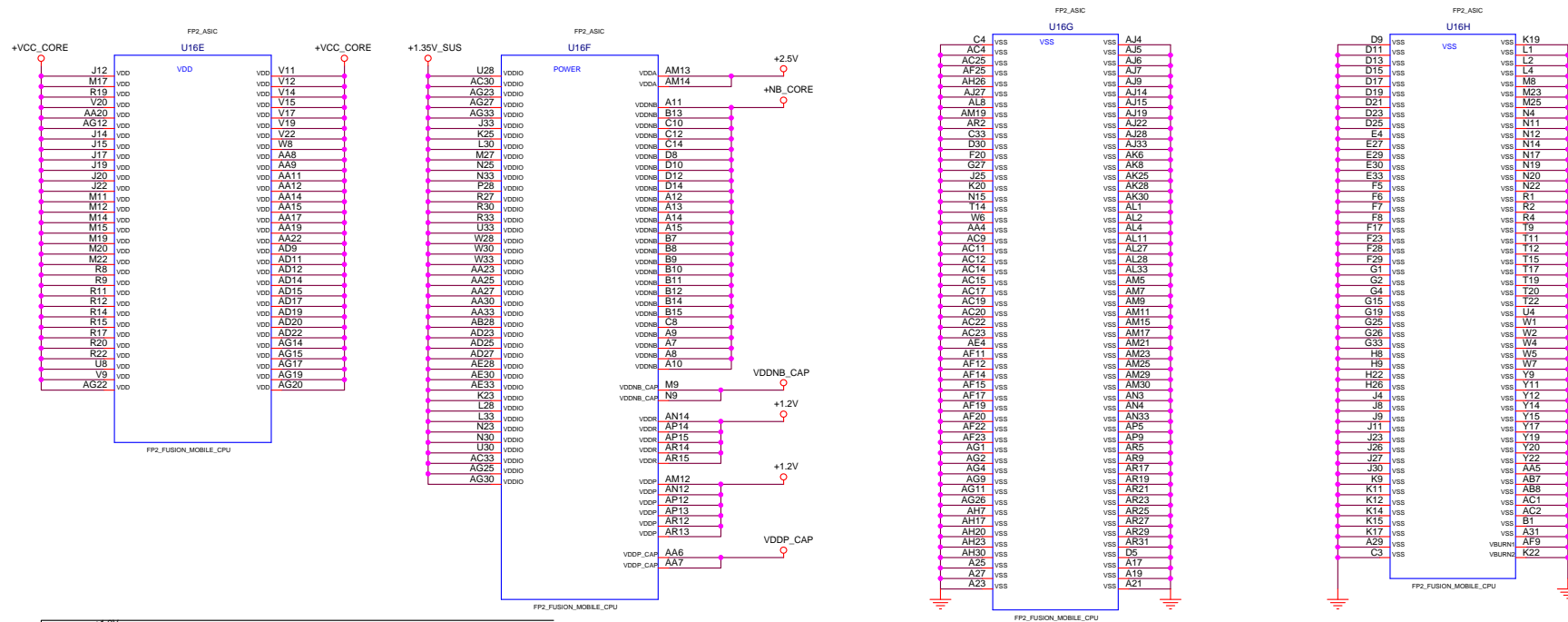
3A-P2
For garbage issue



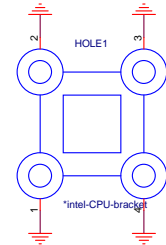
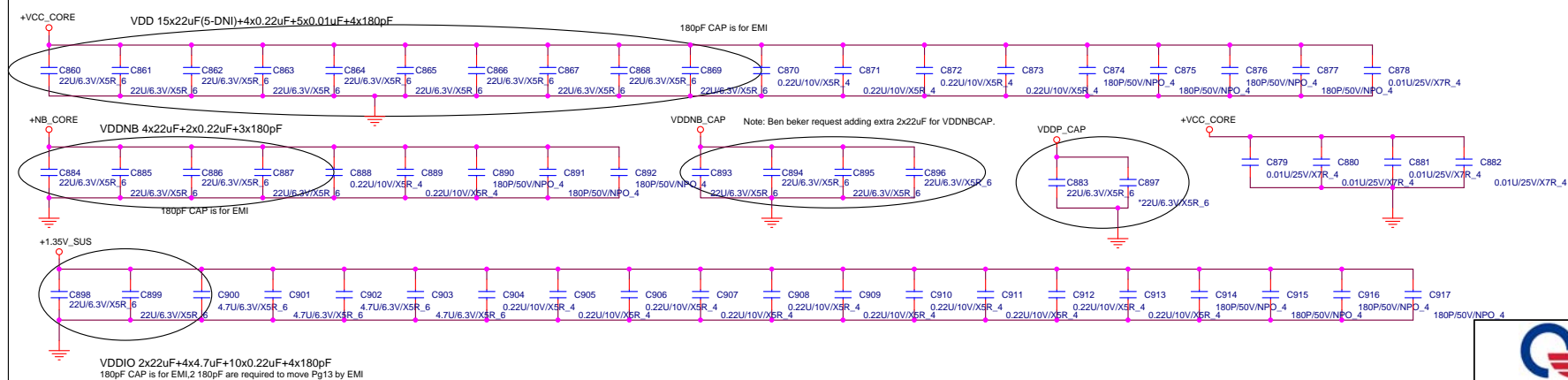
1.Level 1 Environment-related Substances Should Never be Used.
2.Recycled Resin and Coated Wire should be procured from Green Partners.

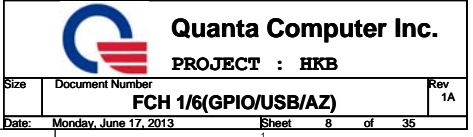






BOTTOM SIDE DECOUPLING





FCH 2/5(UMI/PCIE/PCI/CLK/LPC)

Place these PICE AC coupling cap close to FCH

PCIE_CALP/N_FCH:55 ohm,<1"

Bolton-M3

Part 1 of 5

PCI CLKs

PCI EXPRESS

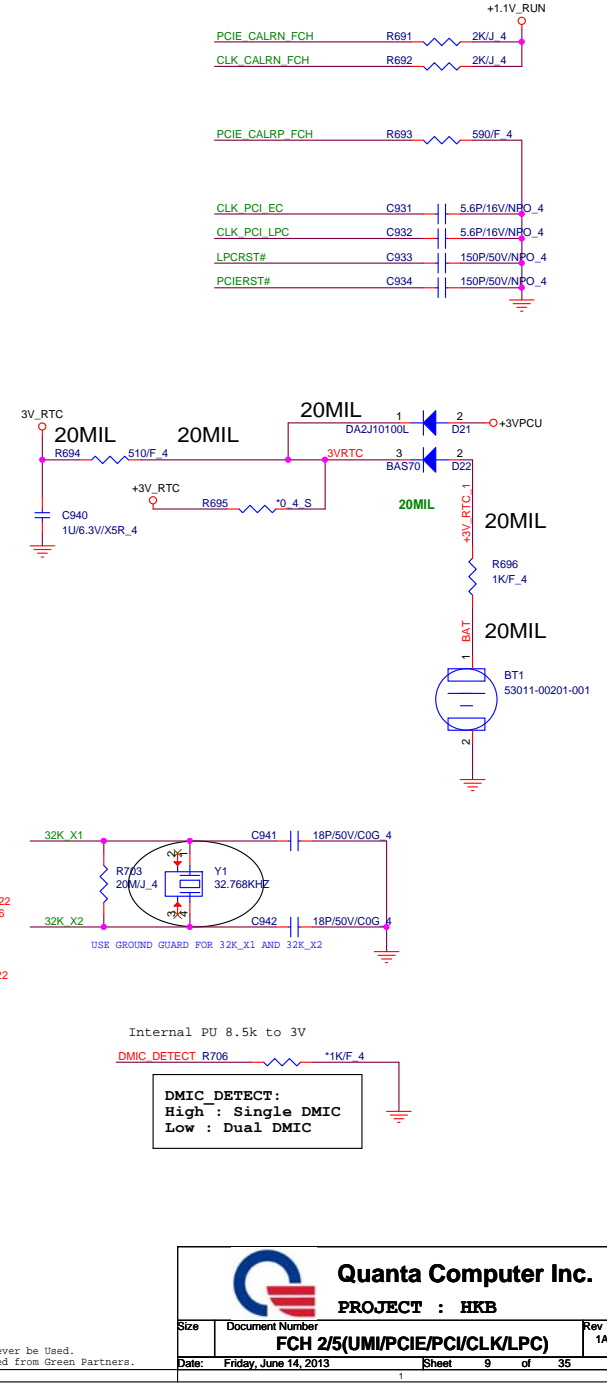
PCI INTERFACE


LPC

APU

PLUS

CLOCK GENERATOR





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Size	Document Number	Rev
	FCH 2/5(UMI/PCIE/PCI/CLK/LPC)	1A
Date:	Friday, June 14, 2013	Sheet 9 of 35

1.Level 1 Environment-related Substances Should Never be Used.
2.Recycled Resin and Coated Wire should be procured from Green Partners.

SATA HDD

SATA ODD

SATA_CALP/N:35 ohm,<1"

Bolton-M3

Part 2 of 5

FCH SPI (CLG)

W25X64FVSSIQ: AKE3EFP0N07 For Quad IO

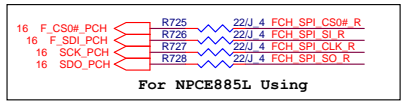
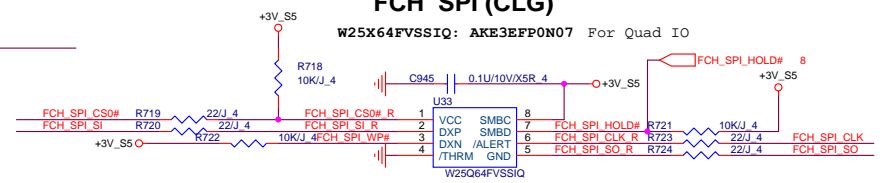
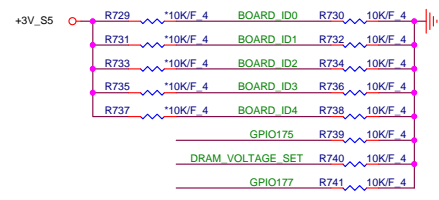
Resistors close to SPI ROM

For NPCE885L Using

SIZE	Board ID0
HKA 14"	0
HKB 15"	1

I/F	Board ID1
eDP	0
LVDS	1

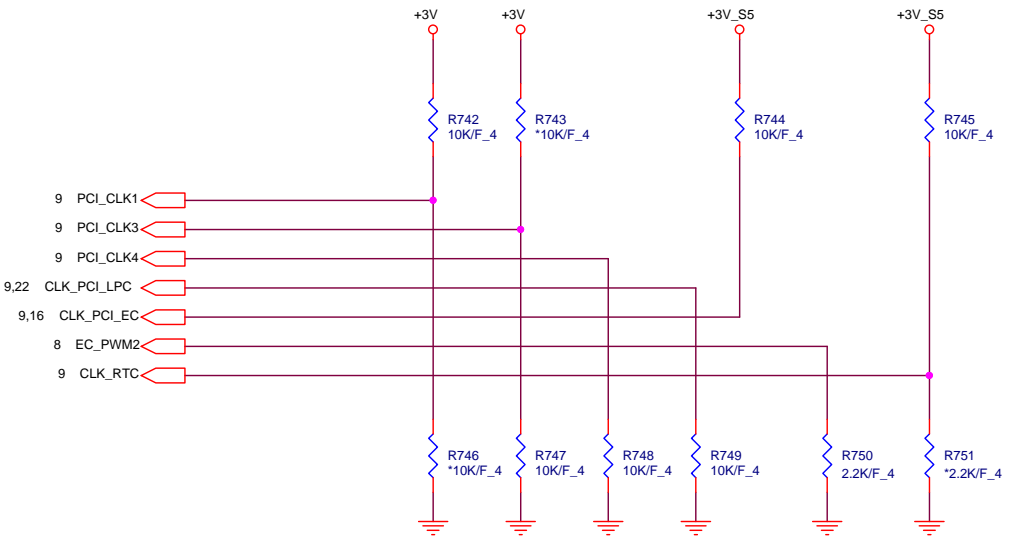
CPU	Board ID2	Board ID3
A4	0	0
A6	0	1
A8	1	0
A10	1	1



STRAPS PINS



OVERLAP COMMON PADS WHERE POSSIBLE FOR DUAL-OP RESISTORS.



REQUIRED STRAPS

		PCI_CLK1		PCI_CLK3	PCI_CLK4	(LPCCLK0) CLK_PCI_LPC	(LPCCLK1) CLK_PCI_EC	EC_PWM2	CLK_RTC
PULL HIGH	-----	ALLOW PCIE Gen2 DEFAULT	-----	USE DEBUG STRAP	Reserved	AMD internal EC ENABLED	CLKGEN ENABLED DEFAULT	LPC ROM	S5 PLUS MODE DISABLED DEFAULT
PULL LOW	-----	FORCE PCIE Gen1	-----	IGNORE DEBUG STRAP DEFAULT	Required setting for integrated clock mode DEFAULT	EC DISABLED DEFAULT	CLKGEN DISABLED	SPI ROM DEFAULT	S5 PLUS MODE enble

1.Level 1 Environment-related Substances Should Never be Used.
2.Recycled Resin and Coated Wire should be procured from Green Partners.

DEBUG STRAPS

FCH has 15K Internal Pull Up for PCI_AD[27:23]



	PCI_AD27		PCI_AD25	PCI_AD24	PCI_AD23
PULL HIGH	USE PCI PLL DEFAULT		normal REFCLK DEFAULT	USE DEFAULT PCIE STRAPS DEFAULT	DISABLE PCI MEM BOOT DEFAULT
PULL LOW	BYPASS PCI PLL		Inverted REFCLK	USE EEPROM PCIE STRAPS	ENABLE PCI MEM BOOT

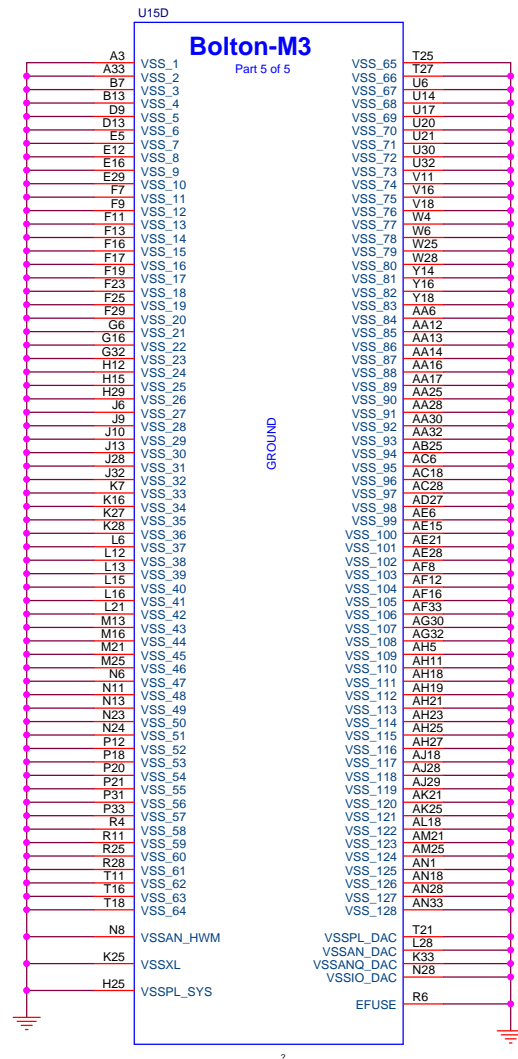
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Size Document Number

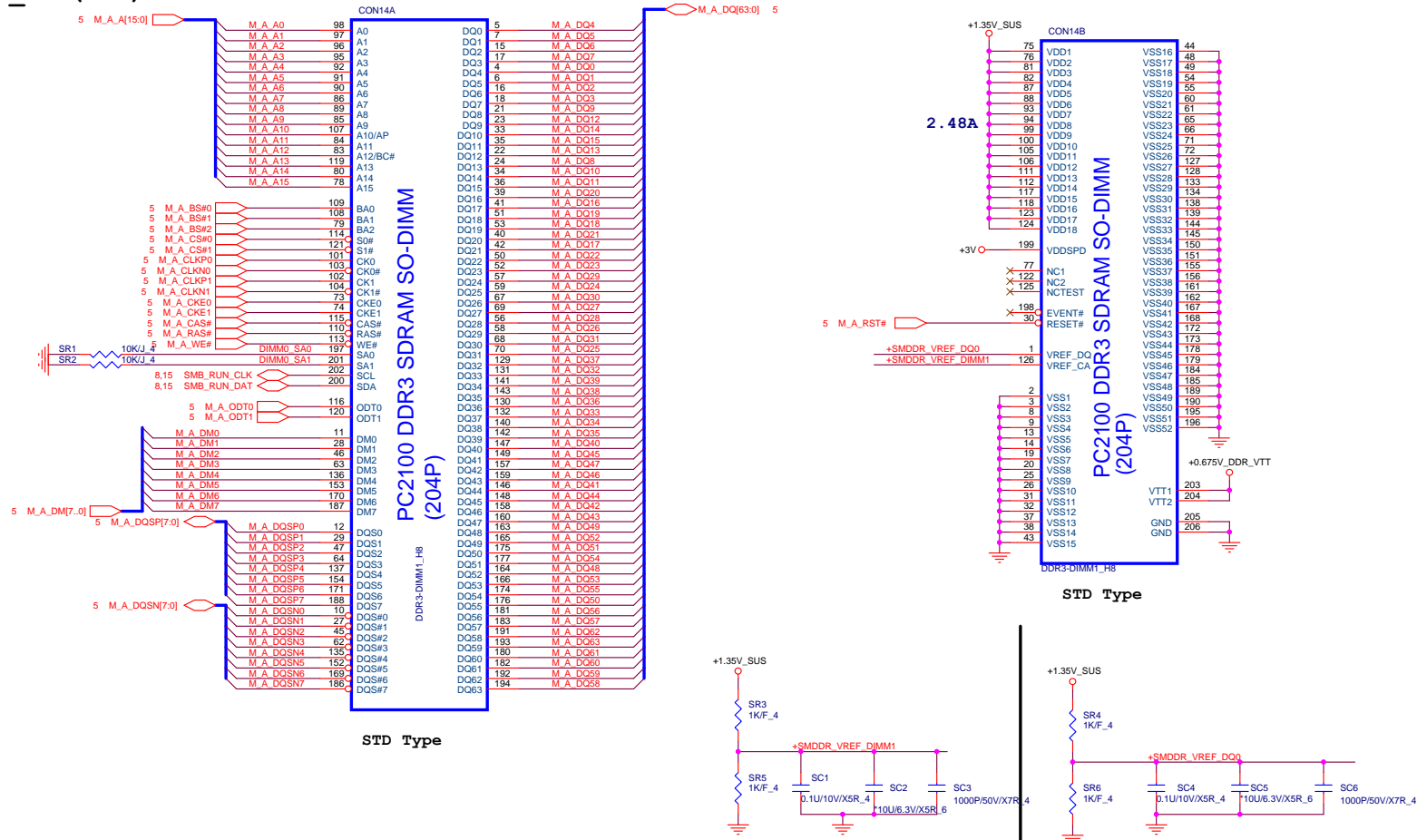
FCH 5/6(Strap)

Date: Friday, June 14, 2013 Sheet 12 of 35

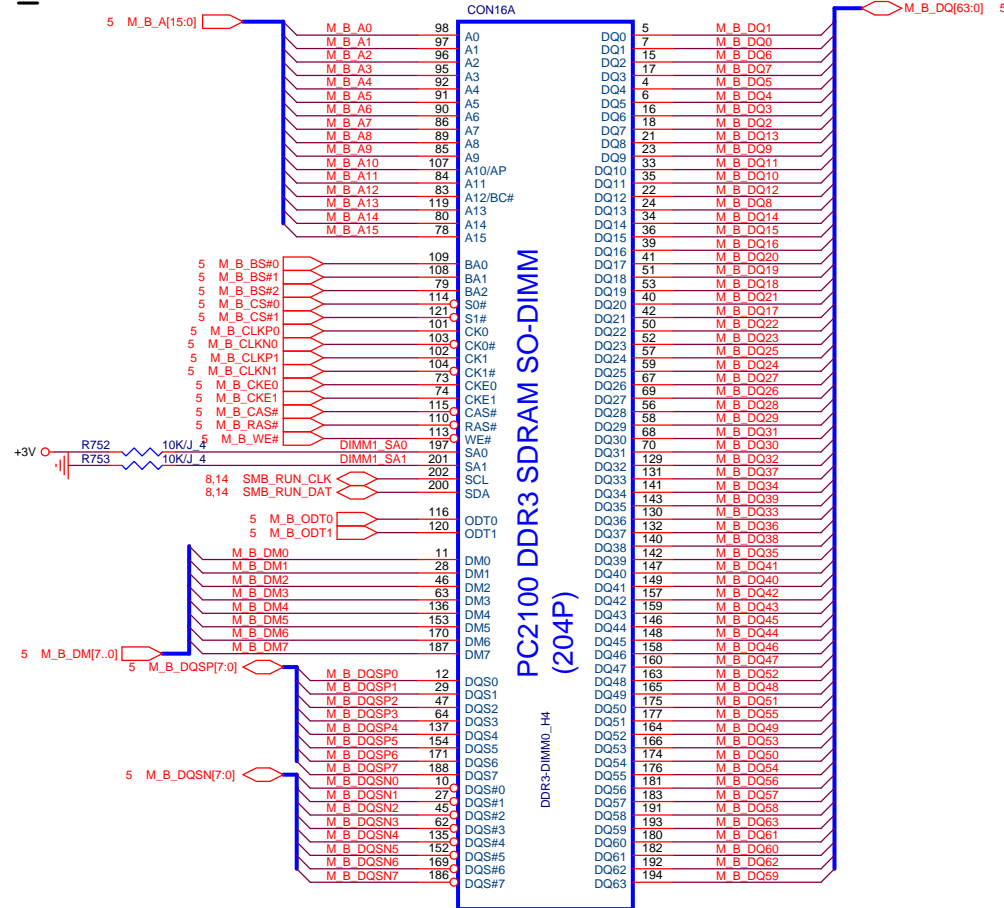
Rev 1A



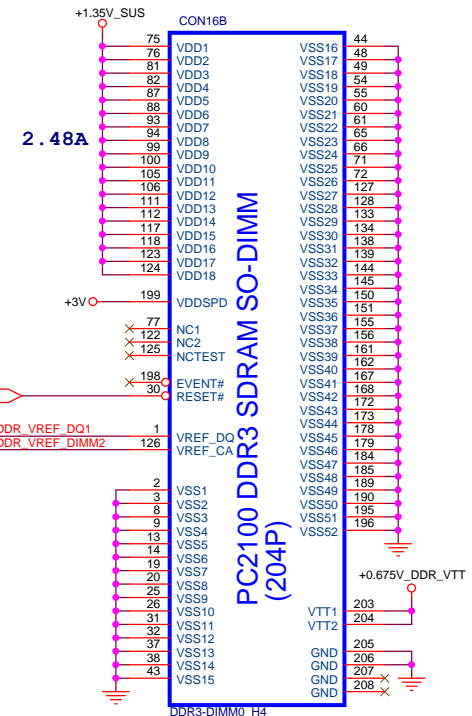
DDR_RVS (DDR)



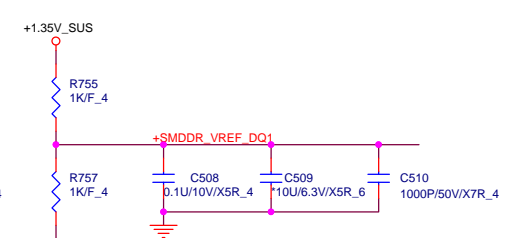
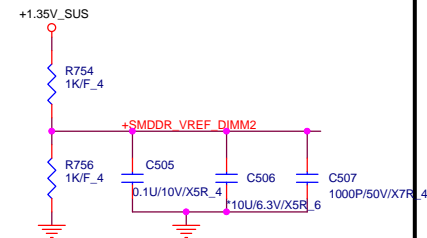
DDR_STD (DDR)



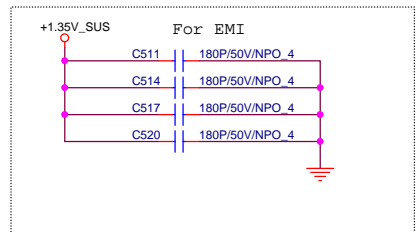
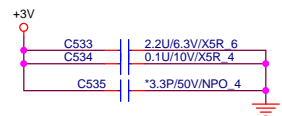
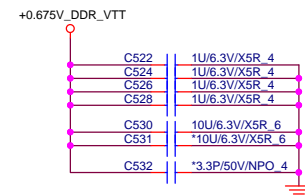
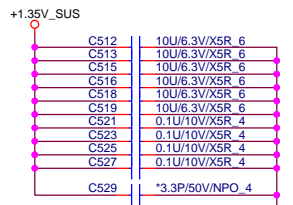
STD Type



STD Type



Place these Caps near So-Dimm1.



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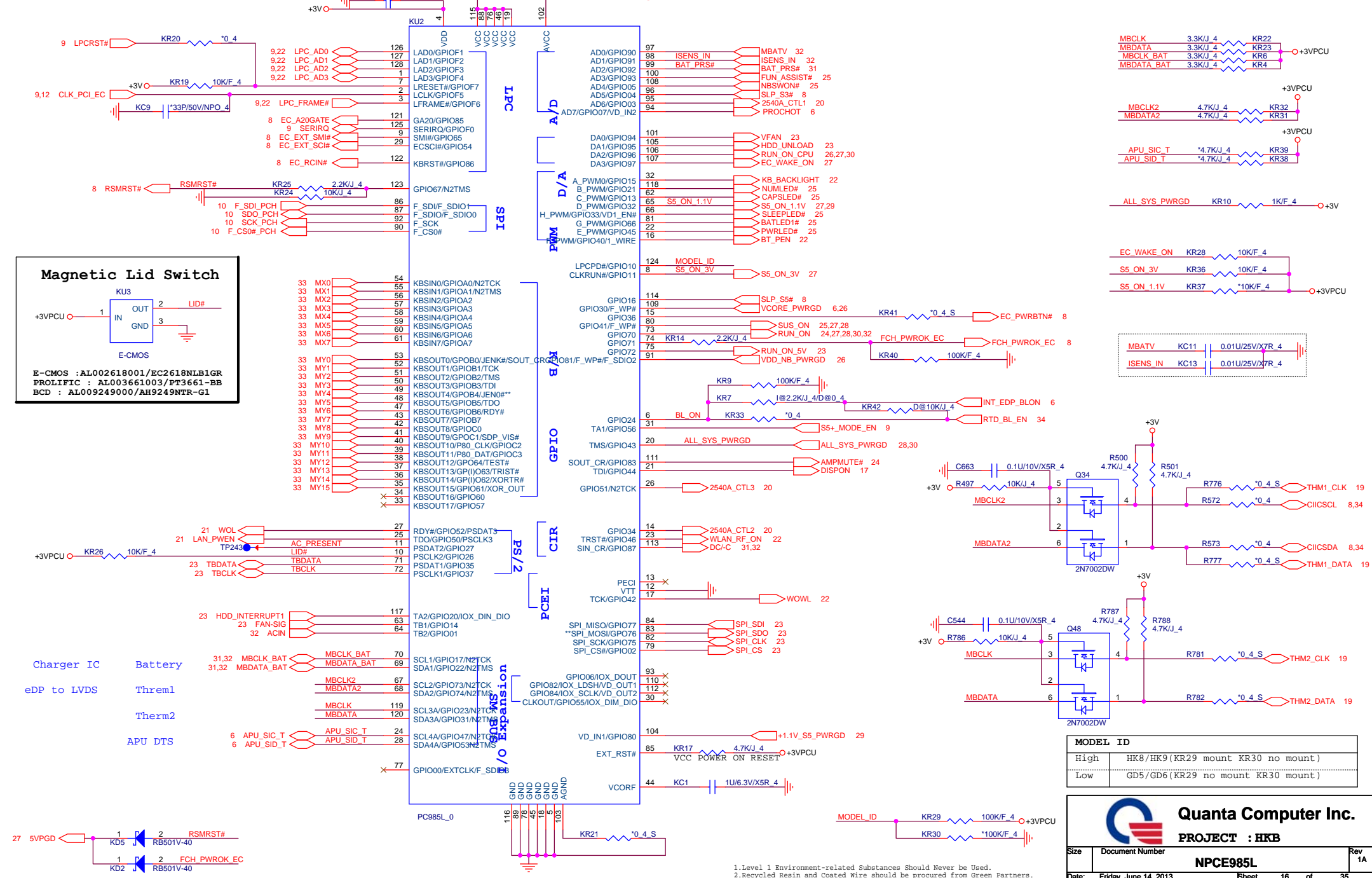
DDRIII SO-DIMM-1

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		1A
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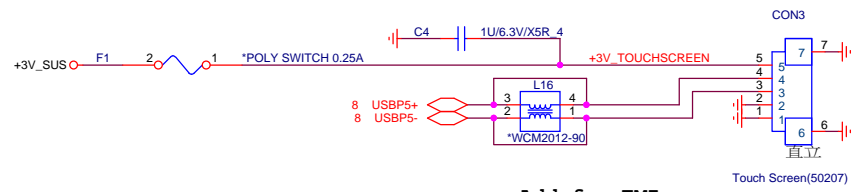
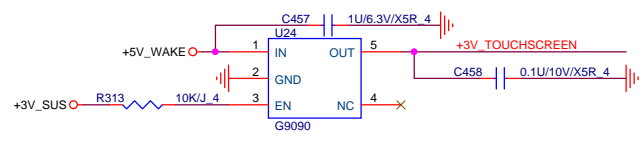
1.Level 1 Environment-related Substances Should Never be Used.
2.Recycled Resin and Coated Wire should be procured from Green Partners.

**** Strapping Pin, Can not pull low.**
Note the input leakage current to the strap pins must be less than 10uA.

Since ECSCI is OD, no need for a back-drive protection diode on this signal. But note there is internal PU in chipset at default



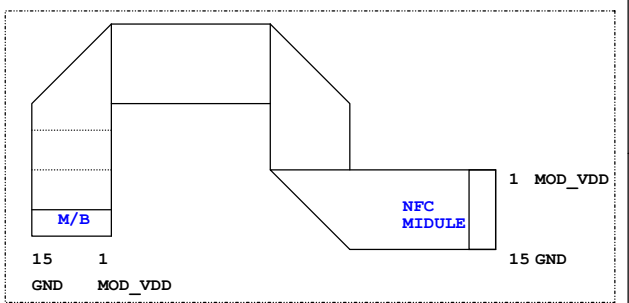
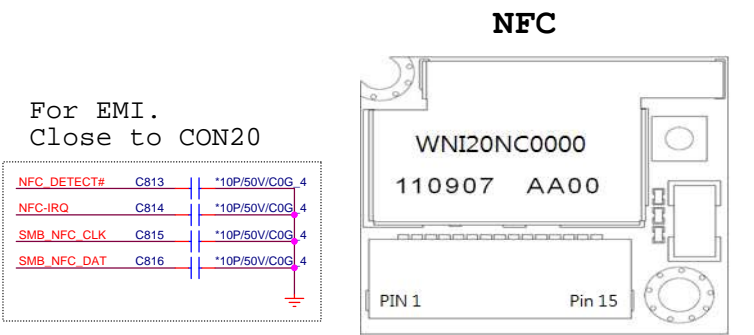
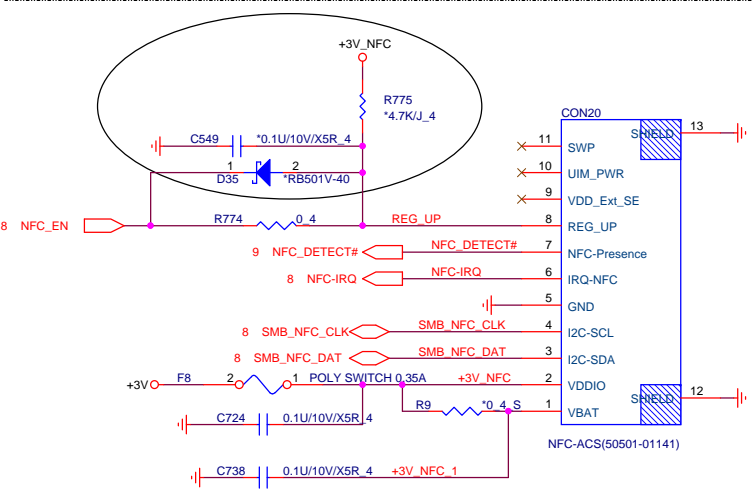
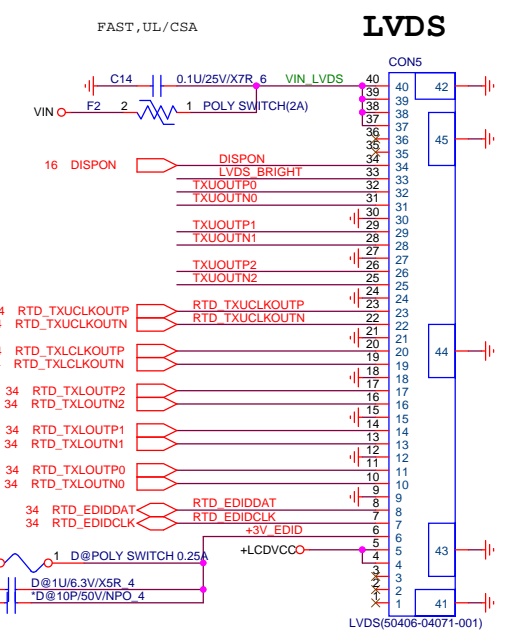
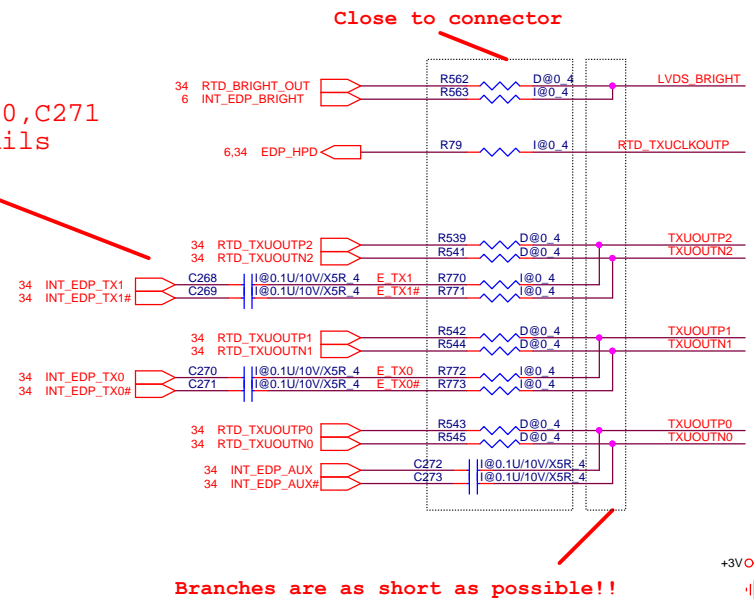
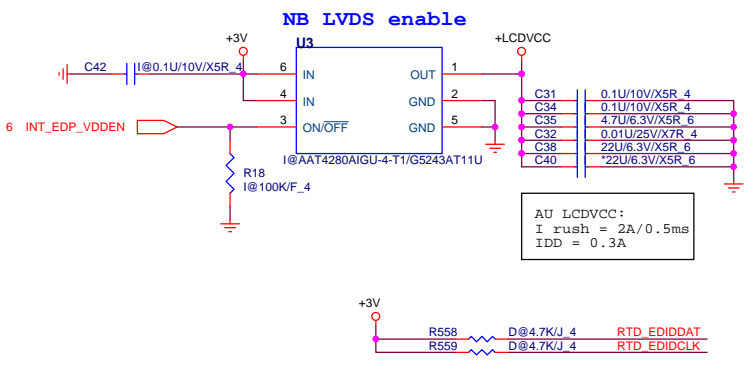
Touch Screen



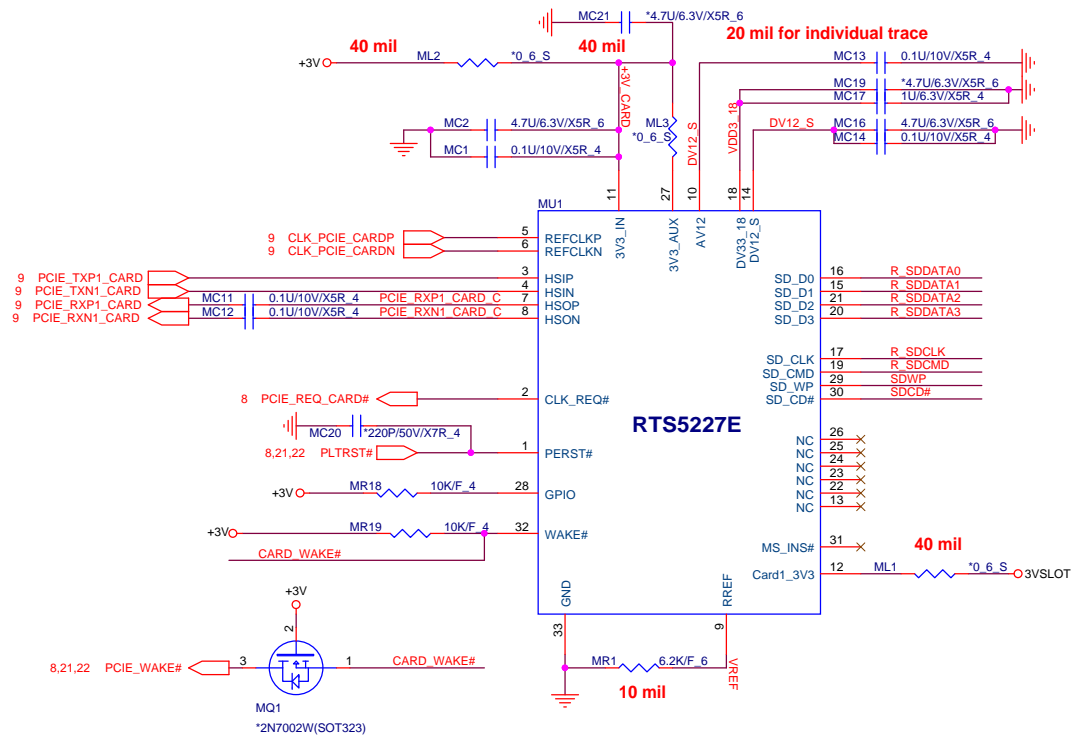
Add for EMI

Camera HD specification
Voltage: Max. 3.6V
Current : Max. 200mA
OCP: 200mA ~ 300mA

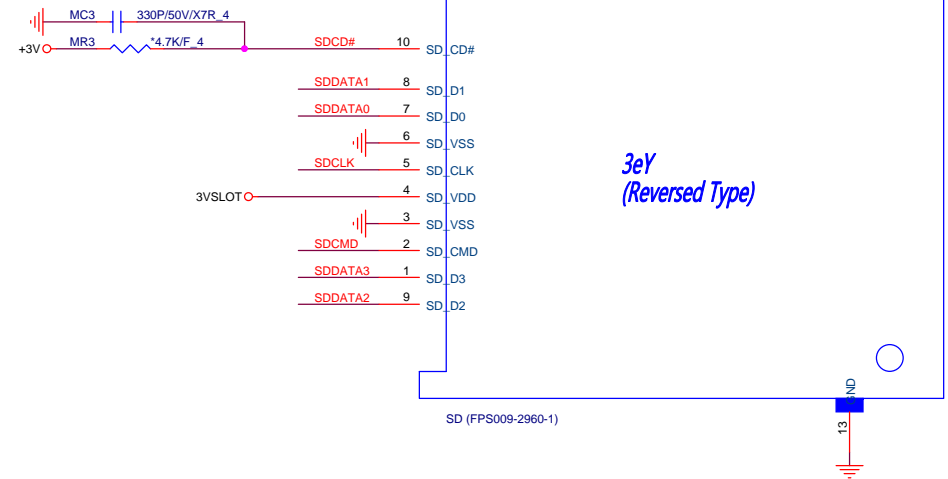
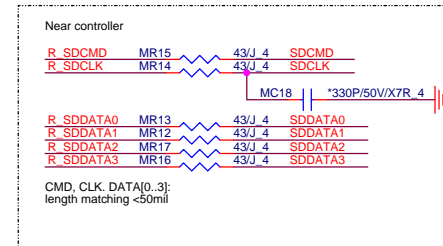
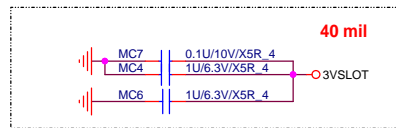
Distance between C268,C269,C270,C271 and CON5 must larger than 500 mils



NFC module :
Vender : Samsung SNC-i20
Power consumption : Max. 160mW/48mA
Power Ripple +/- 50mV



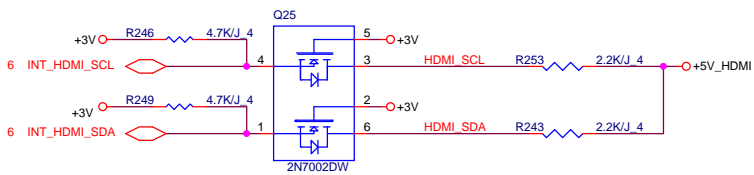
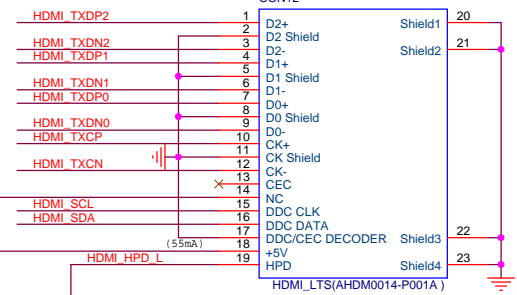
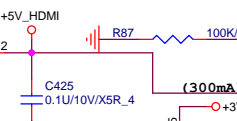
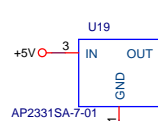
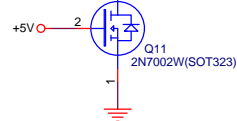
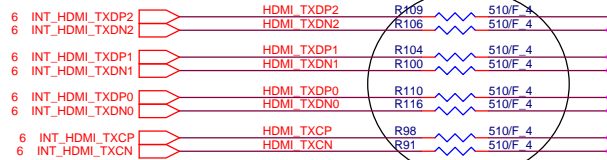
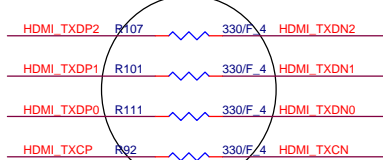
These component need
to close to Slot



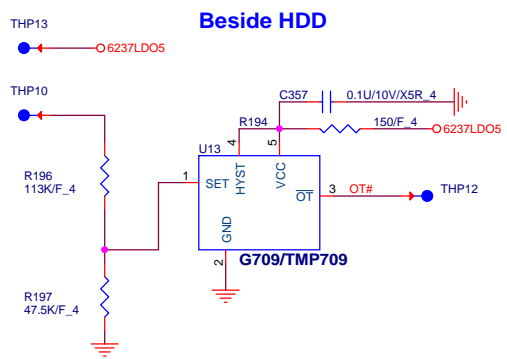
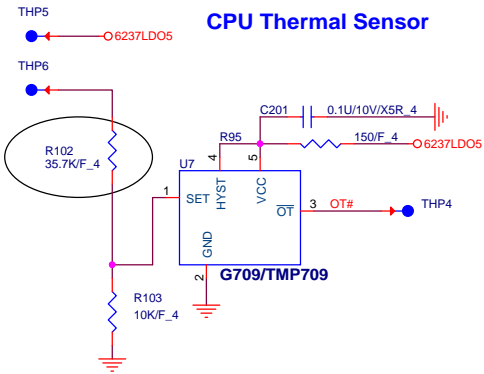
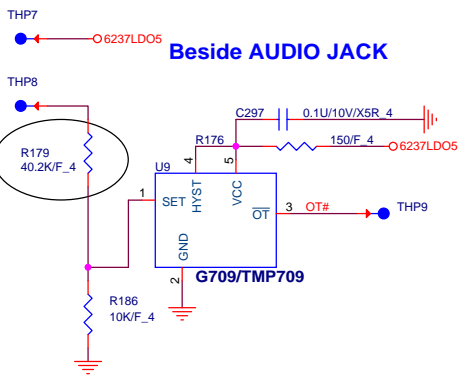
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Card Reader(RTS5227E)

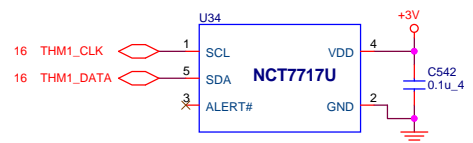


H/W Thermal Protect

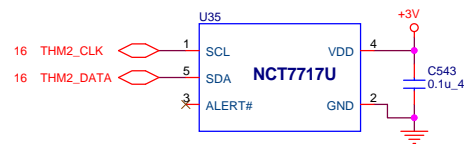


Thermal Request

Close to FIN



Far away heat portion



$$RSET(k\Omega) = 0.0012T^2 - 0.9308T + 96.147$$

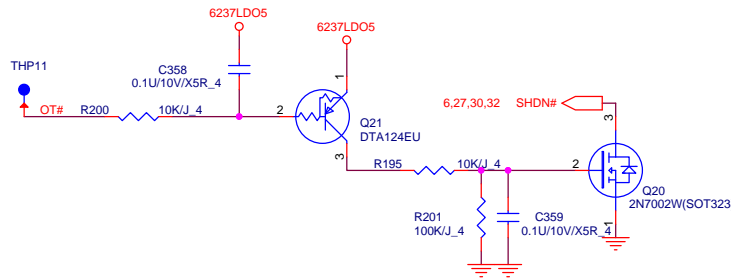
95	18.5K
100	15K
107	10.3K
110	8.2K

DIS SKU

Location of IC	Temp	R-Set	Parts in BOM	Max	Min
Near CPU sensor temp	70	R208=36.87K	36.5K	71	70
Near GFX sensor temp	65	R146=40.72K	40.2K	66.3	65.1
Near AUDIO sensor temp	60	R345=44.62K	44.2K	61.2	60

UMA SKU

Location of IC	Temp	R-Set	Parts in BOM	Max	Min
Near CPU sensor temp	81	R208=28.63K	28K	82.3	81.4
Near AUDIO sensor temp	58	R345=46.2K	46.4K	58.4	57.1



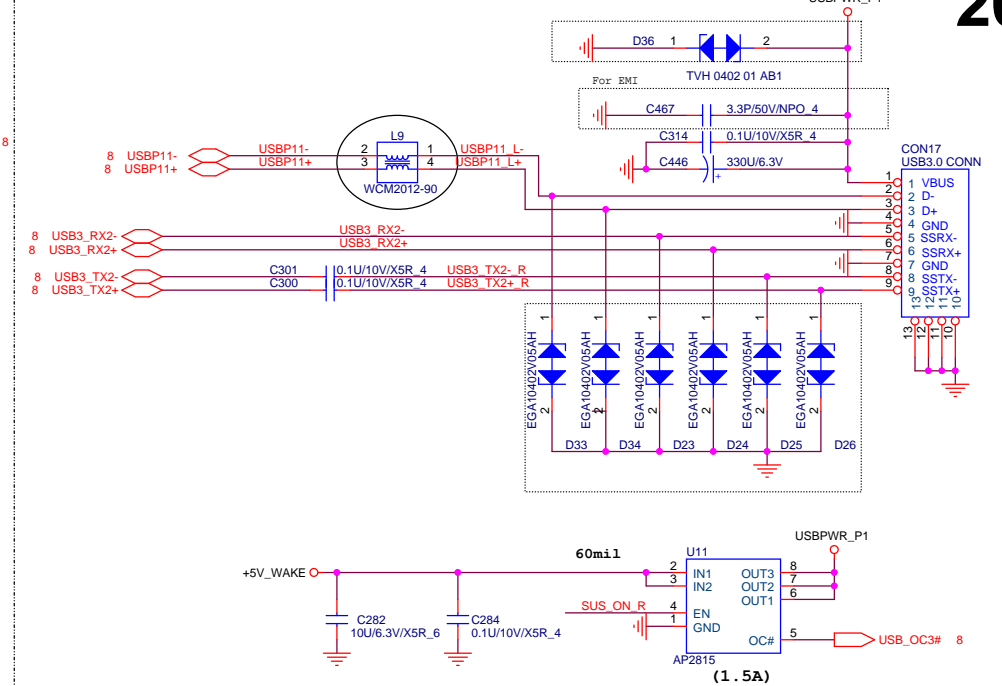
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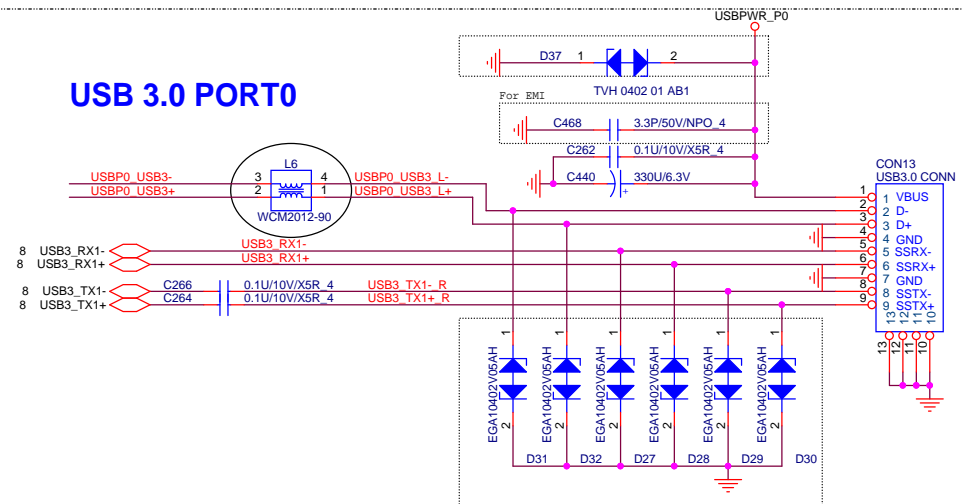
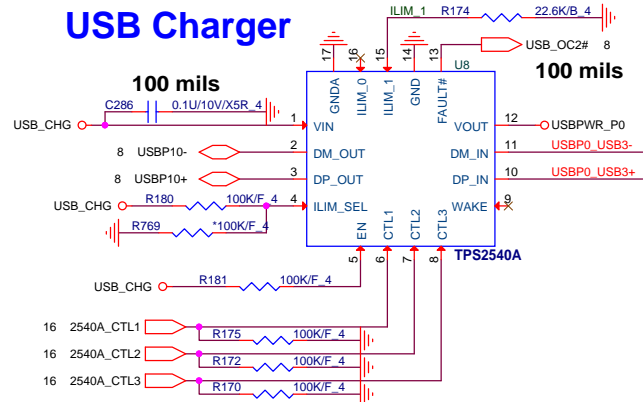
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	HDMI/Thermal	1A
Date:	Tuesday, June 18, 2013	Sheet 19 of 35

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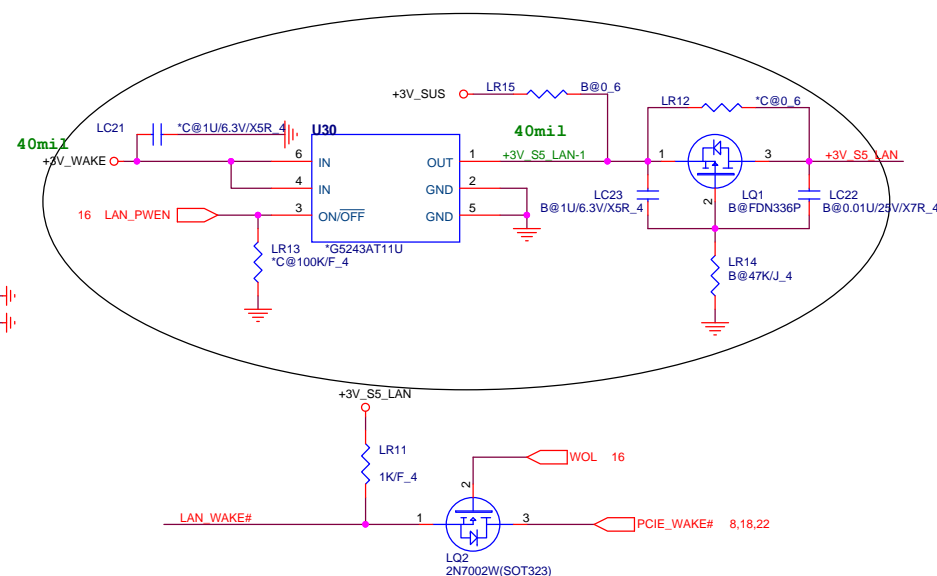


USB 3.0 PORT0



System State	USB Battery Charging Setting			
	Disable	C(1 2 3)	Enable	C(1 2 3)
S0	SDP	(X 1 0)	CDP	(1 1 1)
S3	SDP	(X 1 0)	DCP BC	(1 0 0)
DS3	Charger OFF	(0 0 0)	DCP BC	(1 0 0)
S4	Charger OFF	(0 0 0)	DCP BC	(1 0 0)
S5	Charger OFF	(0 0 0)	DCP BC	(1 0 0)

ILIM_SEL (I LIMIT(A)= 48000/R)		
HI	I_LIM_1	
LO	I_LIM_0	48000/22.6K=2.123A

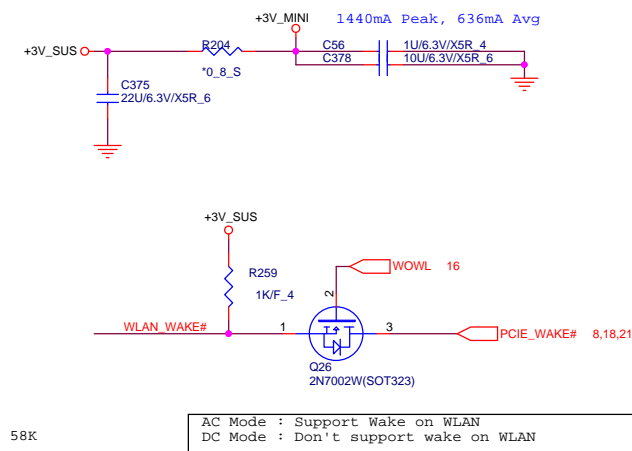
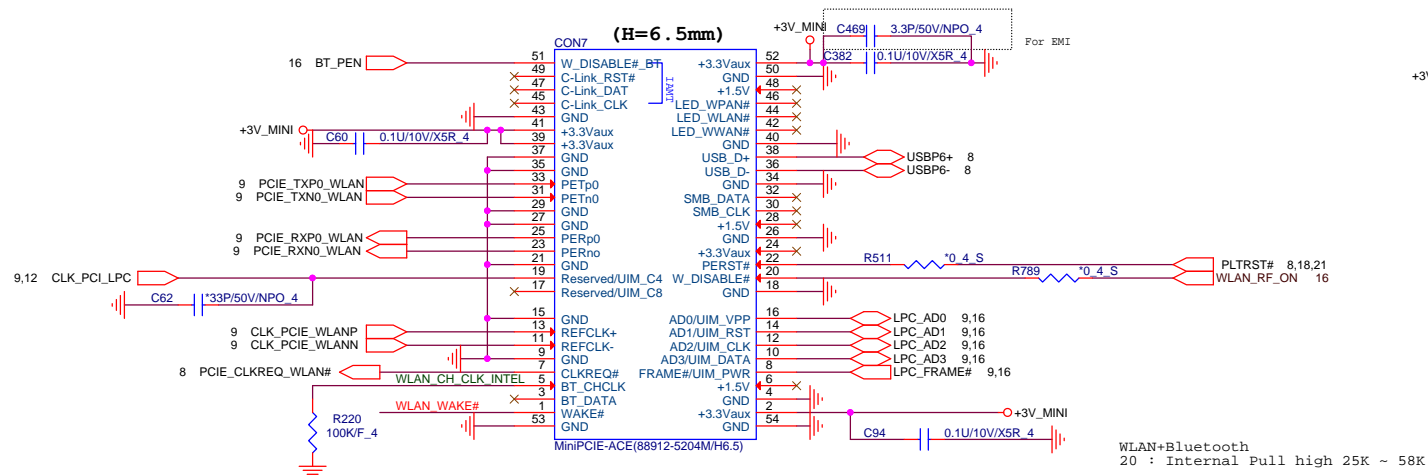


The schematic diagram shows the internal connections of the RJ45_AOP(C100CE-10806-L) module. The module is represented by a blue box labeled 'CON10' with pins 1 through 10. The connections are as follows:

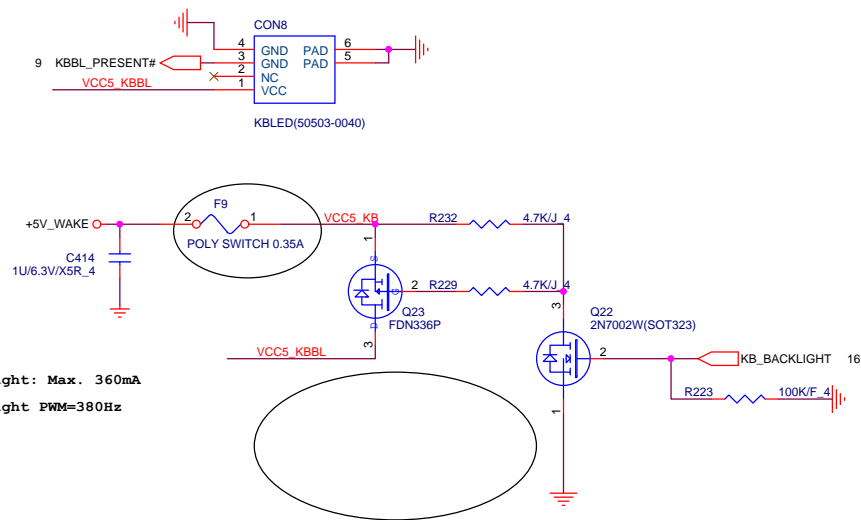
- Power Connections:**
 - VCC (3.3V) is connected to pin 1.
 - GND is connected to pin 10.
- Network Connections:**
 - MDI_TXP0 (TX0+) is connected to pin 2.
 - MDI_TXN0 (TX0-) is connected to pin 3.
 - MDI_TXP1 (TX1+) is connected to pin 4.
 - MDI_TXN1 (TX1-) is connected to pin 5.
 - MDI_TXP2 (TX2+) is connected to pin 6.
 - MDI_TXN2 (TX2-) is connected to pin 7.
 - MDI_TXP3 (TX3+) is connected to pin 8.
 - MDI_TXN3 (TX3-) is connected to pin 9.

The module is labeled 'RJ45_AOP(C100CE-10806-L)'.

WLAN/WIMAX/WIDI



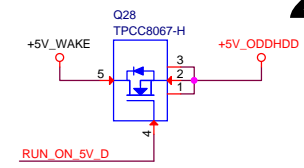
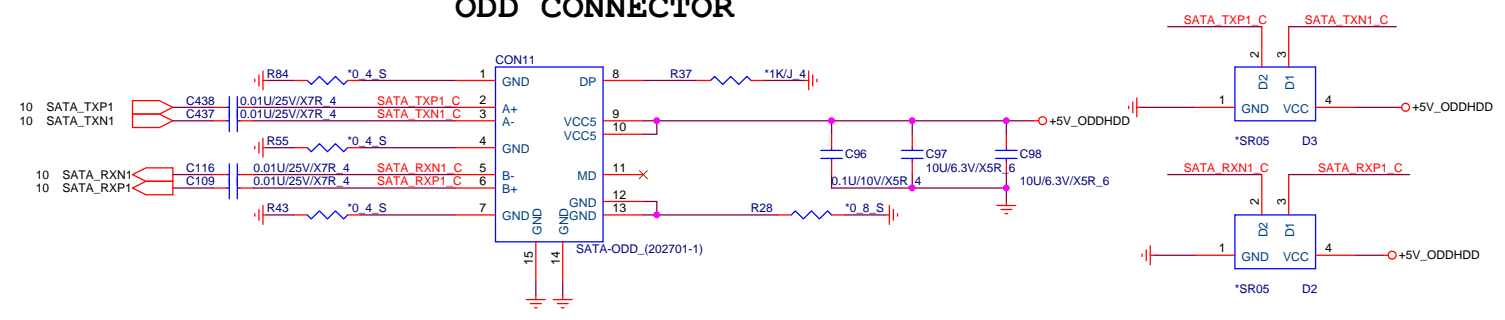
KB BACKLIGHT



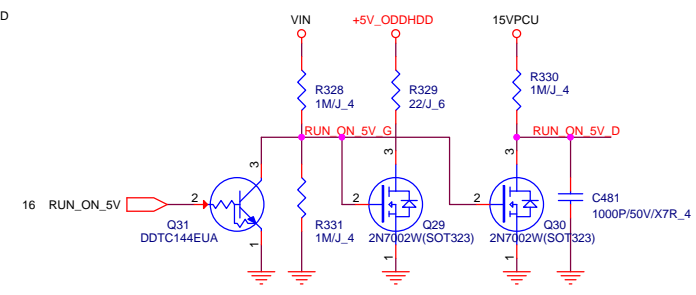
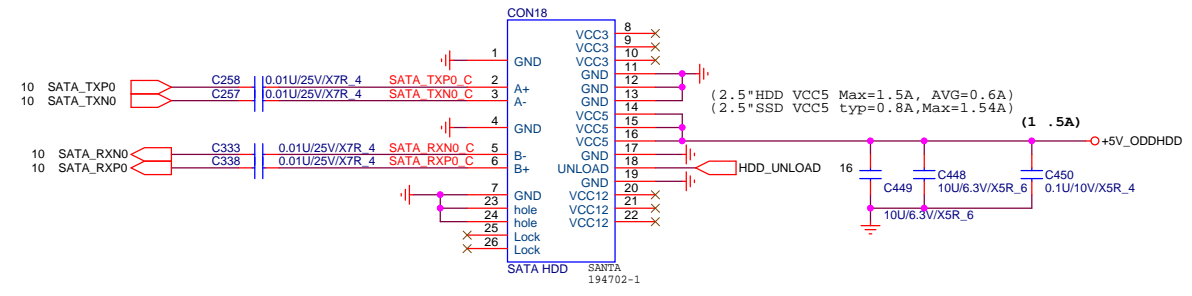
KB Backlight: Max. 360mA
KB Backlight PWM=380Hz



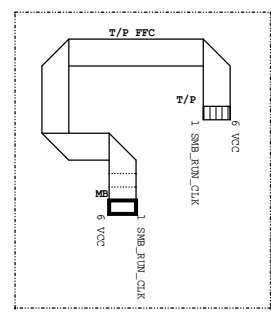
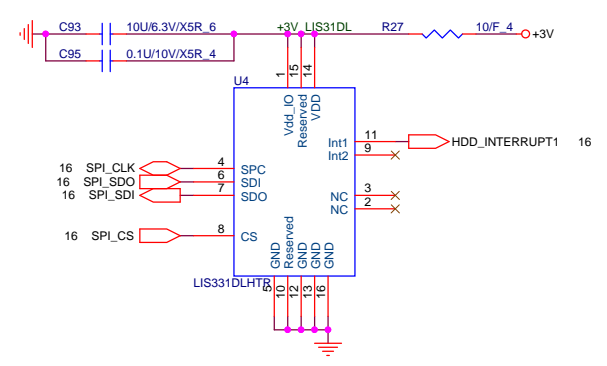
ODD CONNECTOR



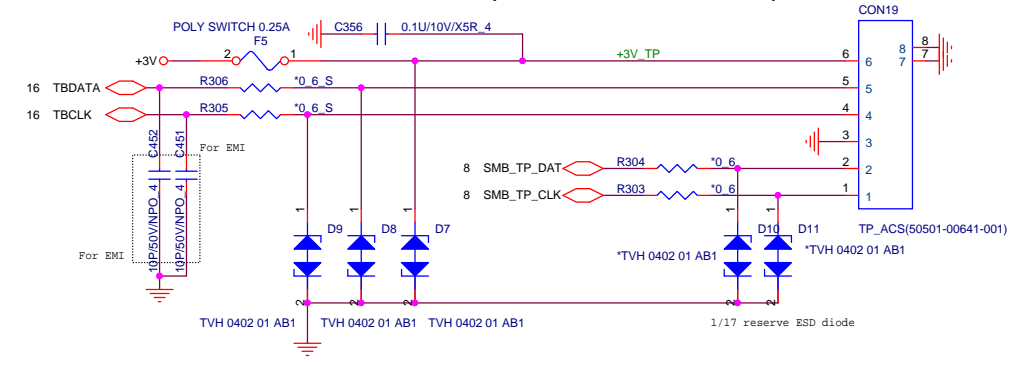
HDD CONNECTOR



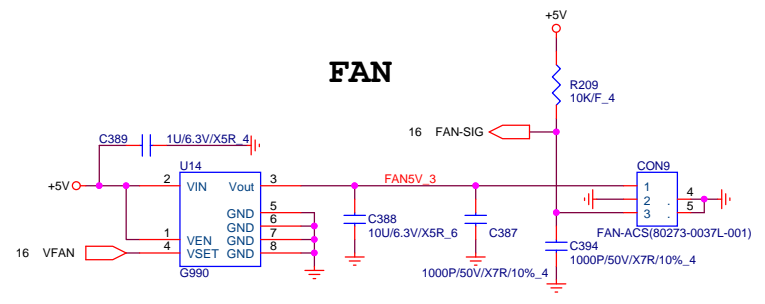
HDD PROTECT SPI INTERFACE



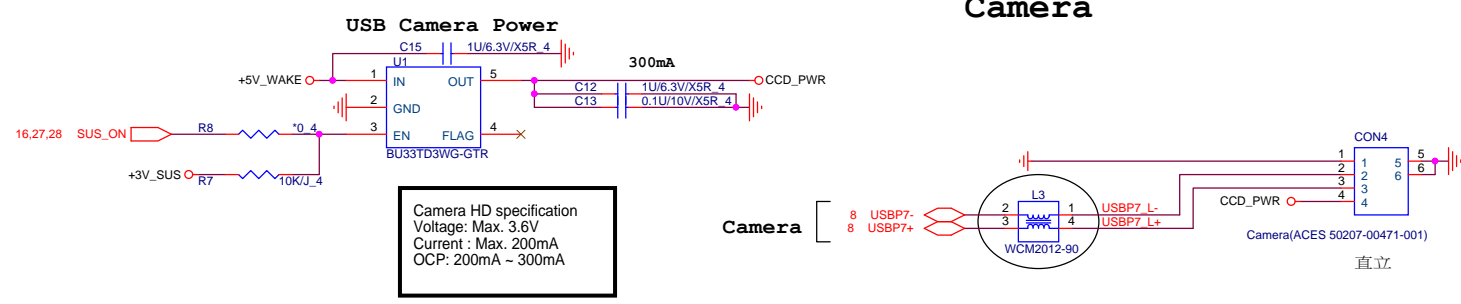
T/P Board to T/P



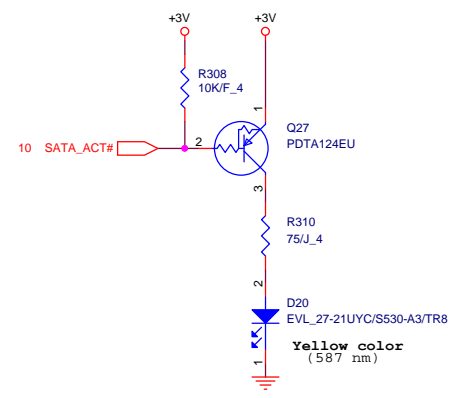
FAN



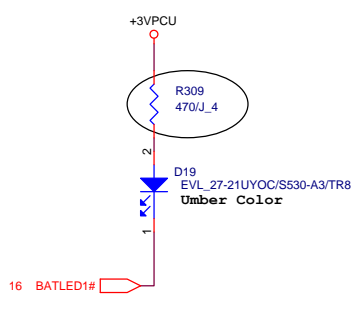
Camera



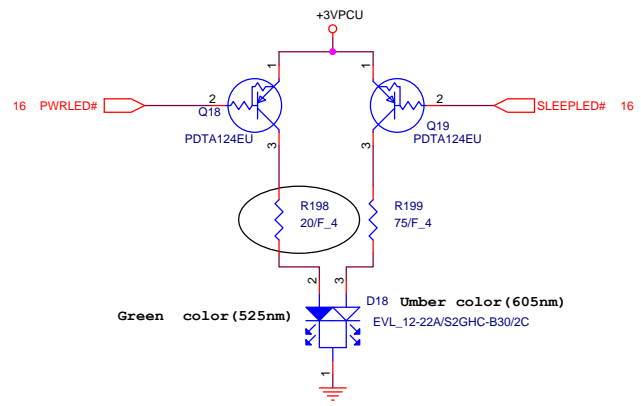
SATA LED



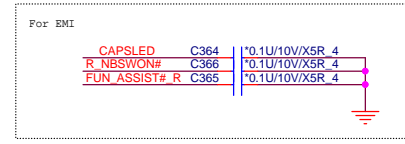
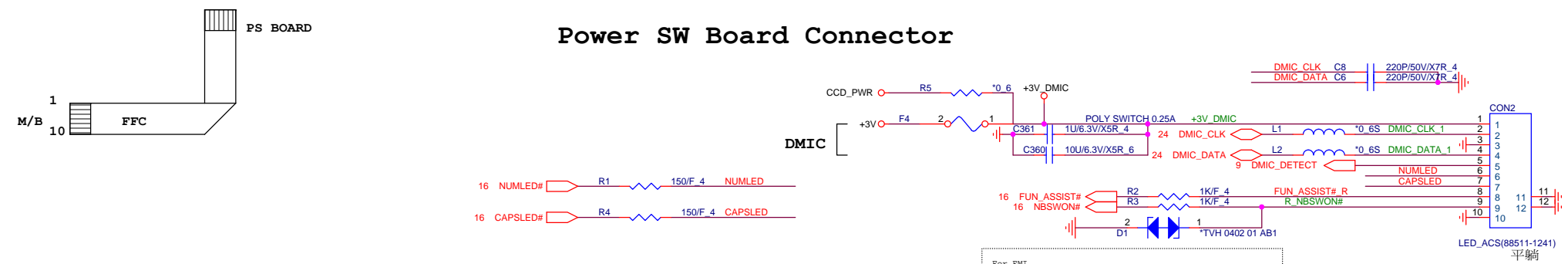
BATTERY LED



Power/Sleep LED

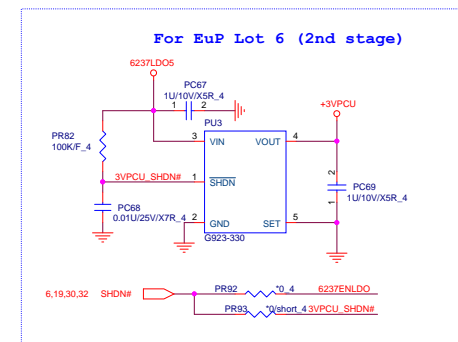
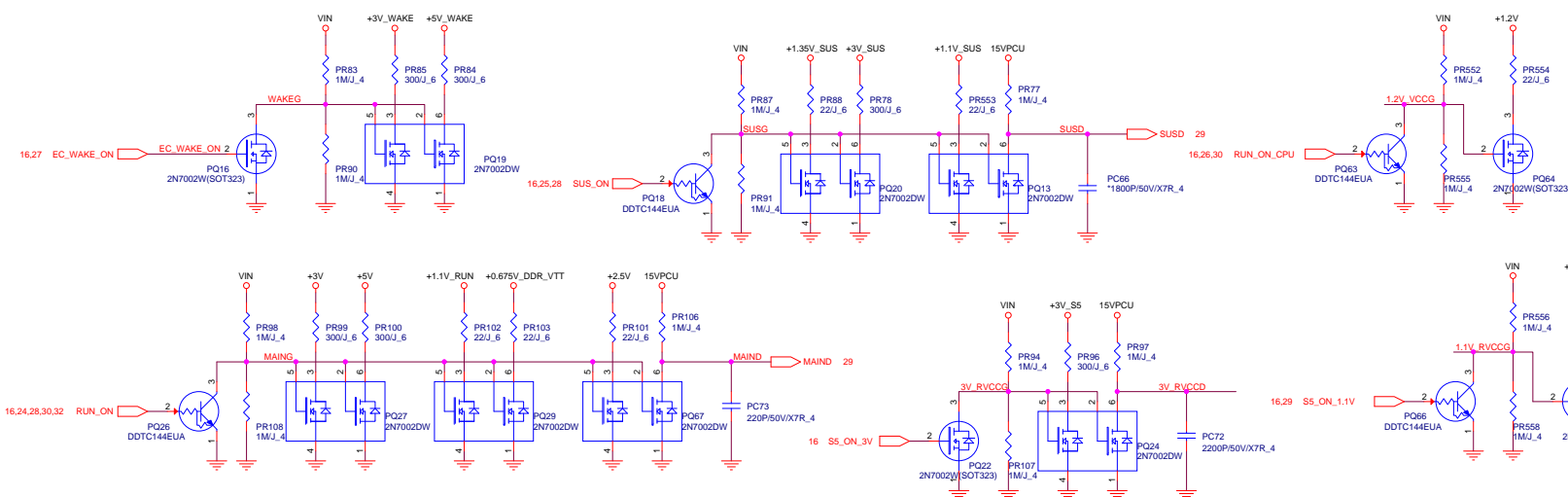
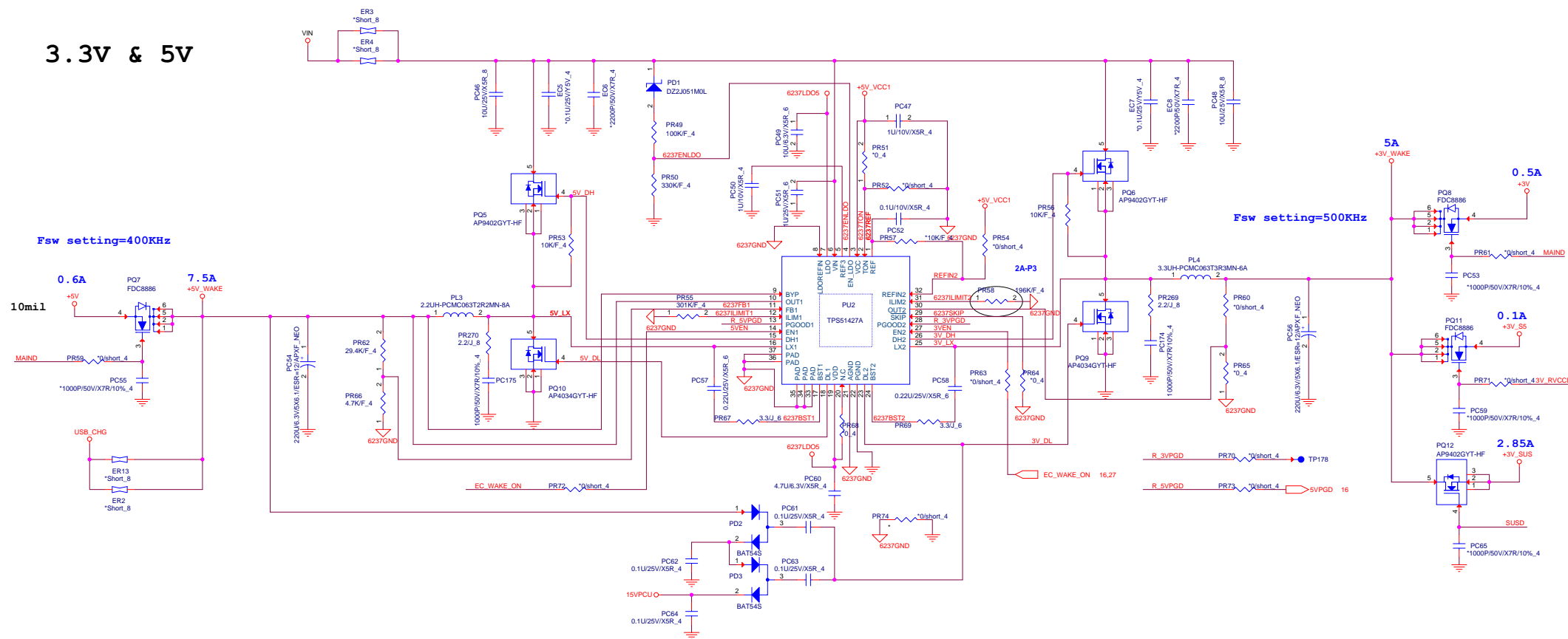


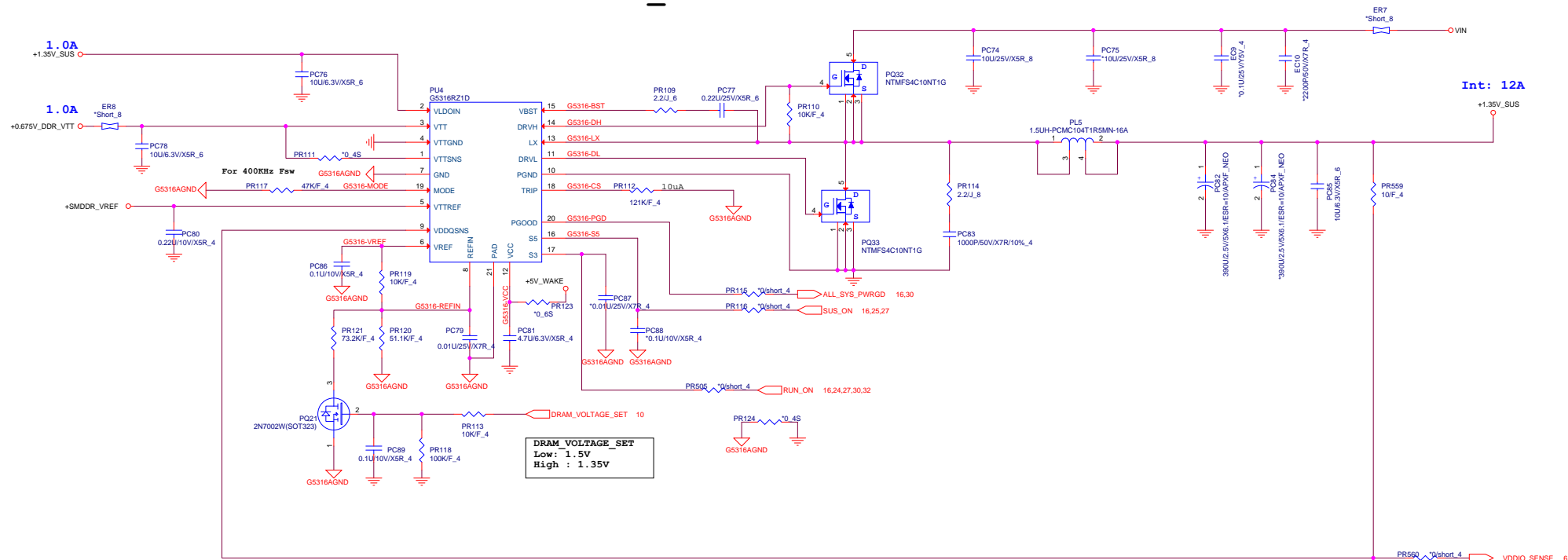
Power SW Board Connector



1.Level 1 Environment-related Substances Should Never be Used.
2.Recycled Resin and Coated Wire should be procured from Green Partners.

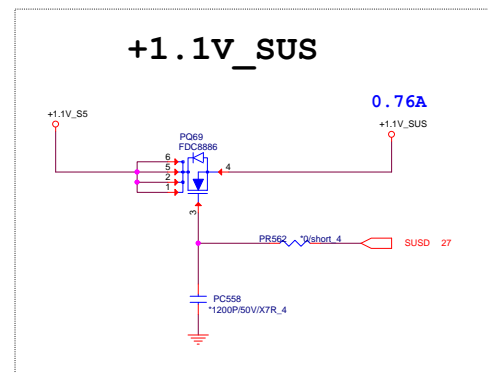
3.3V & 5V





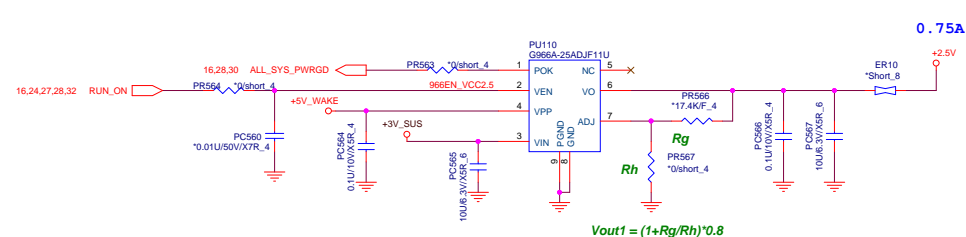
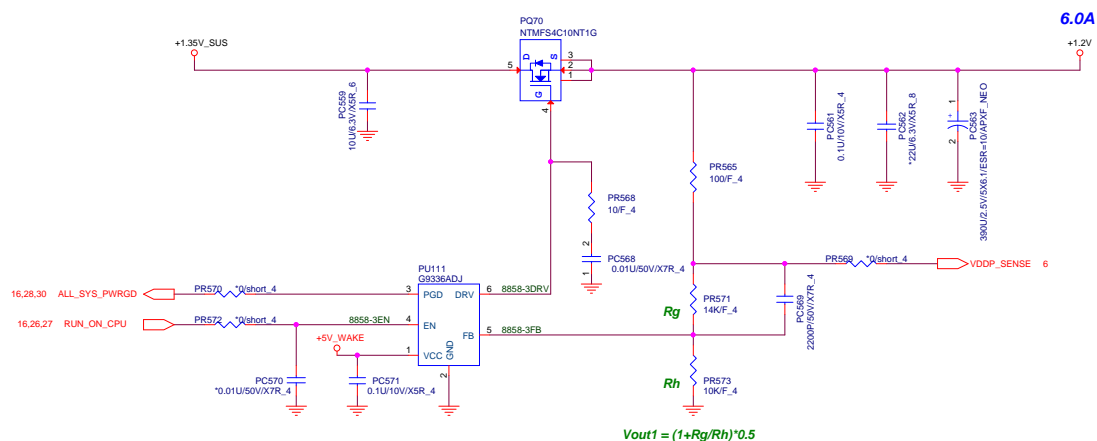
MODE	Resistor on Mode	Fsw	Discharge Mode
3	200Kohm	400KHz	Tracking discharge
2	100Kohm	300KHz	
1	68Kohm	300KHz	Non-tracking discharge
0	47Kohm	400KHz	

STATE	S3	S5	1.5VSUS	VITREF	VIT
S0	1	1	On	On	On
S3	0	1	On	On	Off/High Z
S4/S5	0	0	Off	Off	Off

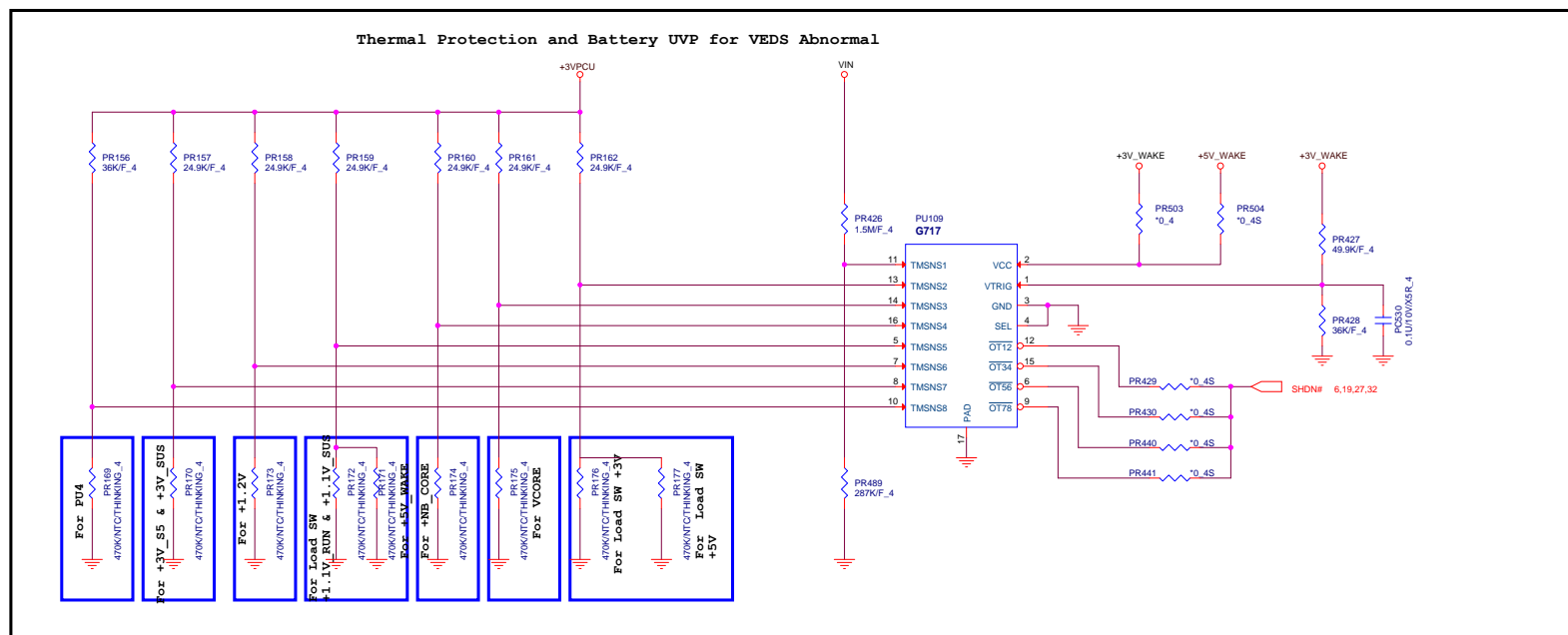


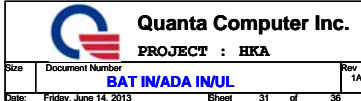
VCC1.2

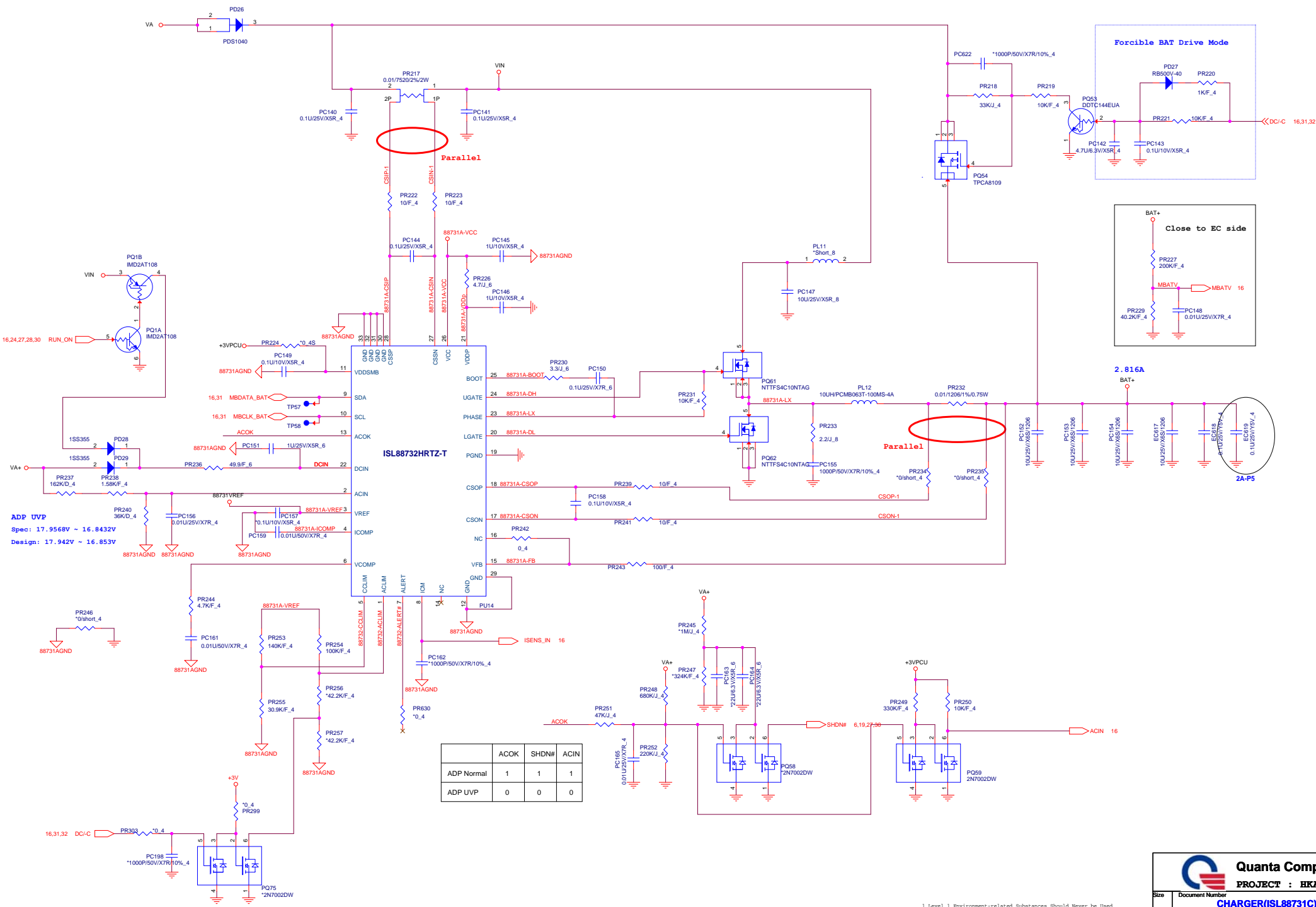
VCC2.5



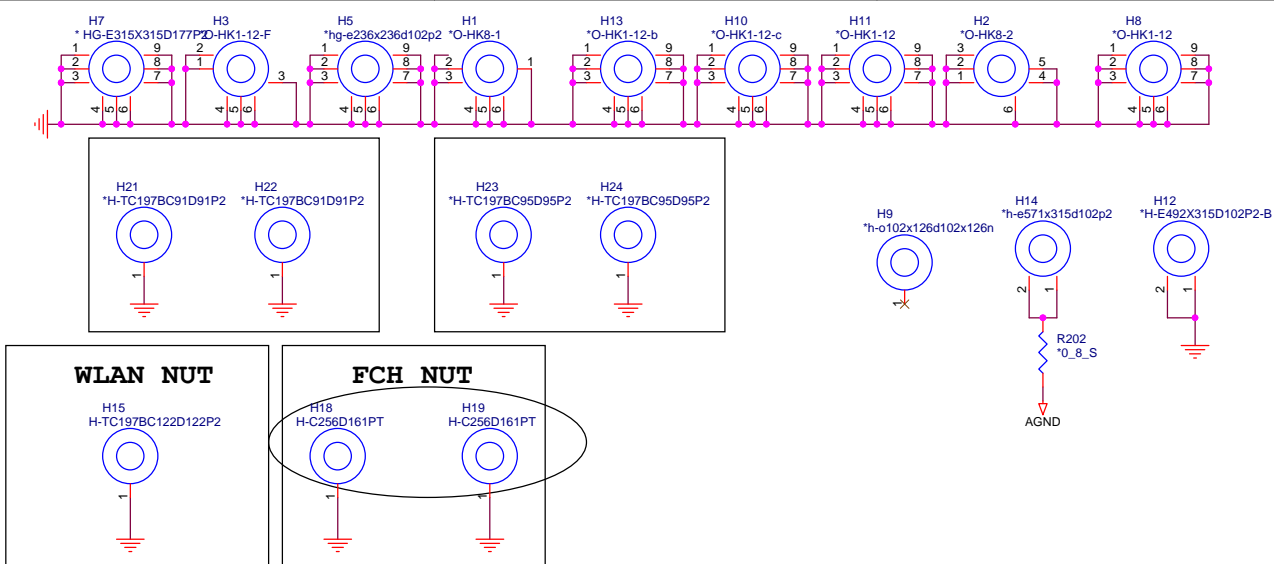
$$V_{out1} = (1 + R_g/R_h) \cdot 0.8$$



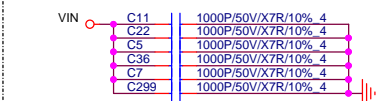
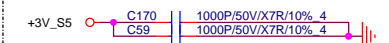
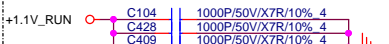
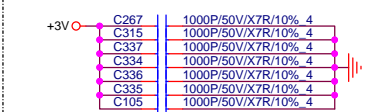
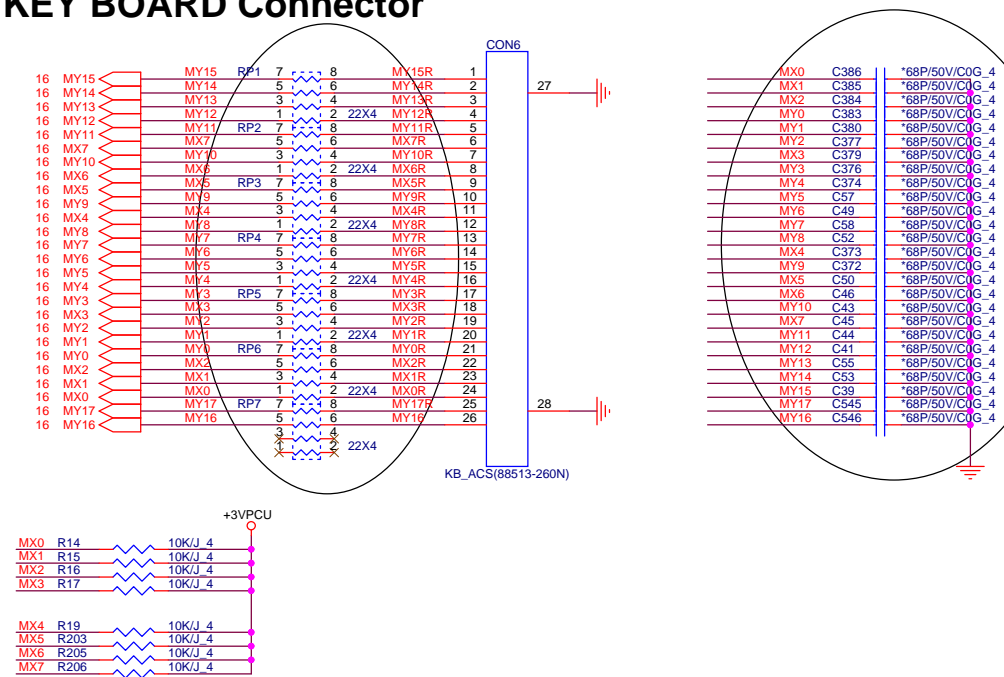





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KEY BOARD Connector





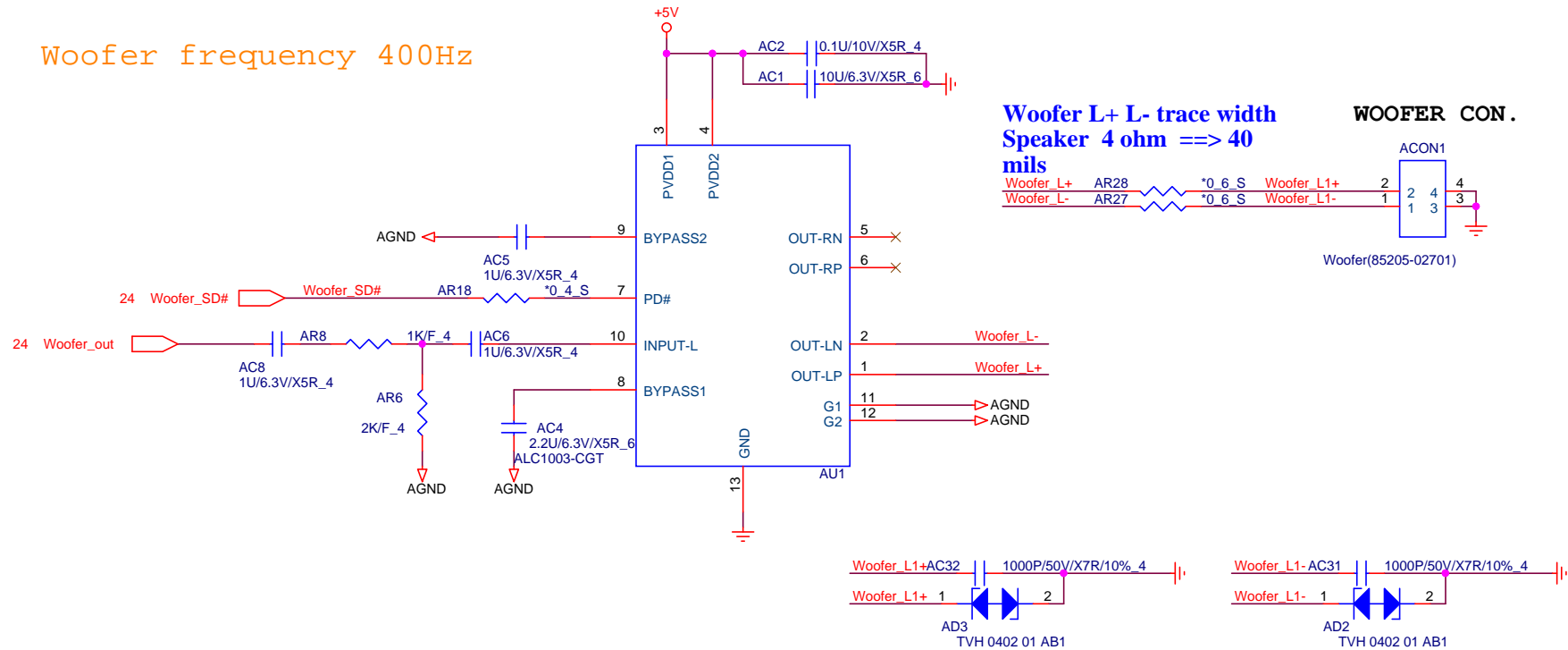
Quanta Computer Inc.

PROJECT : HKB

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	HOLE/EMI/KB	1A
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1. Level 1 Environment-related Substances Should Never be Used.
2. Recycled Resin and Coated Wire should be procured from Green Partners.

Woofers frequency 400Hz



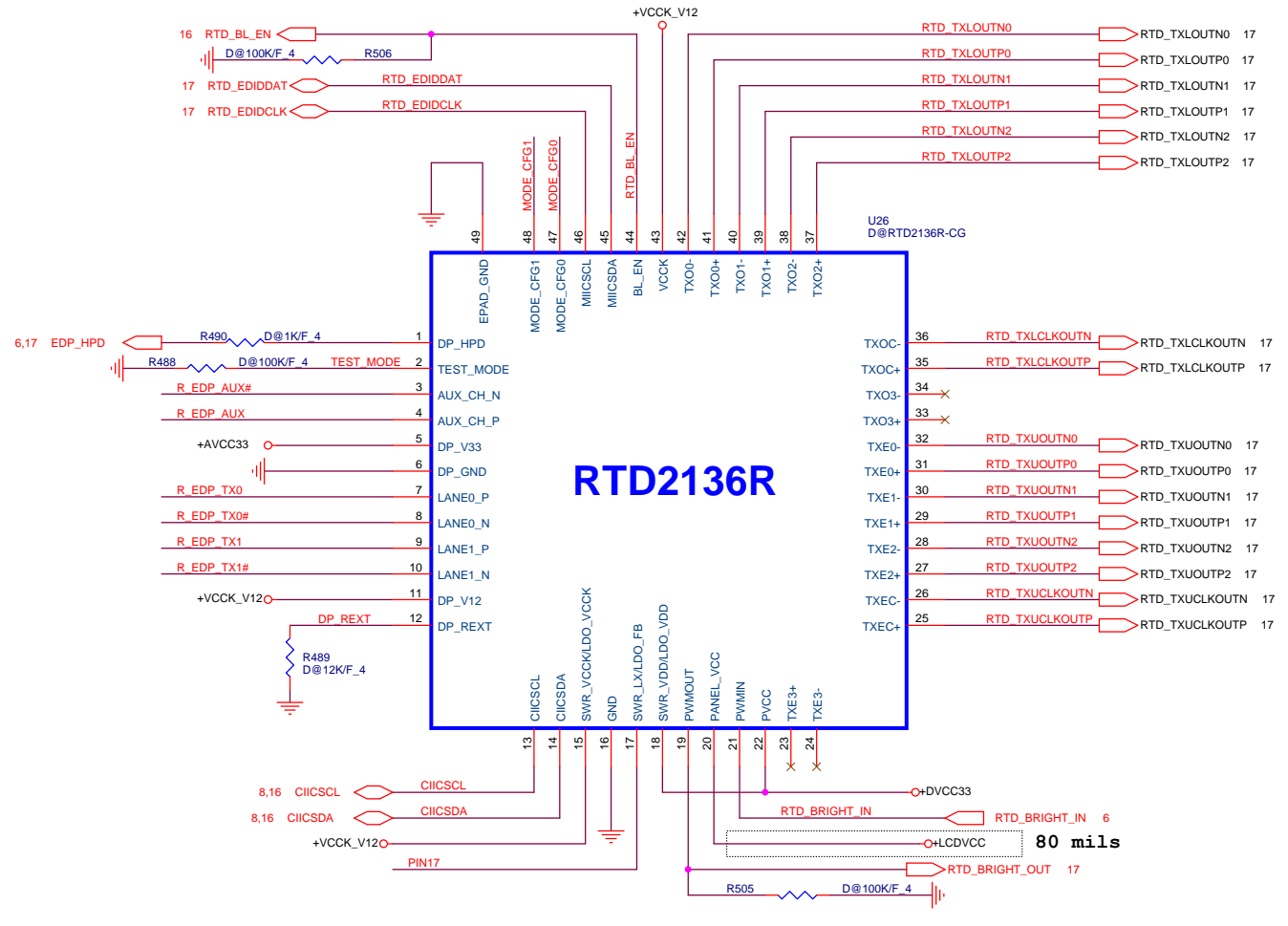
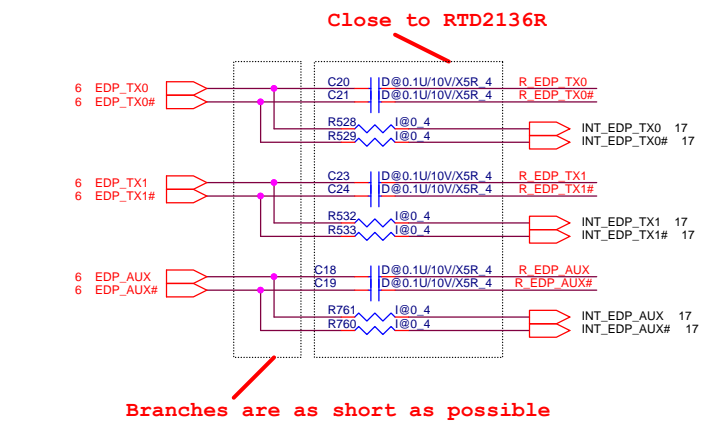
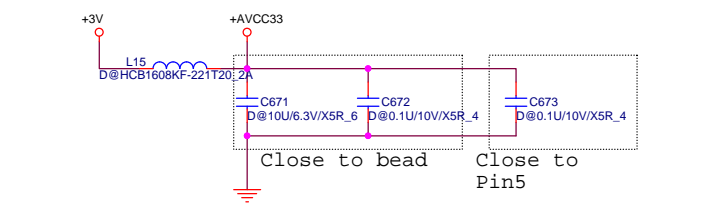
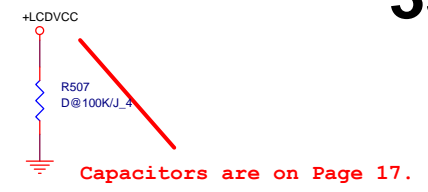
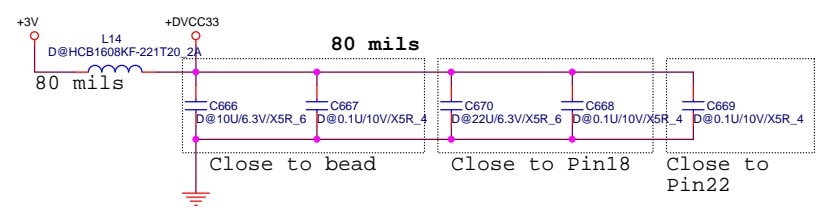
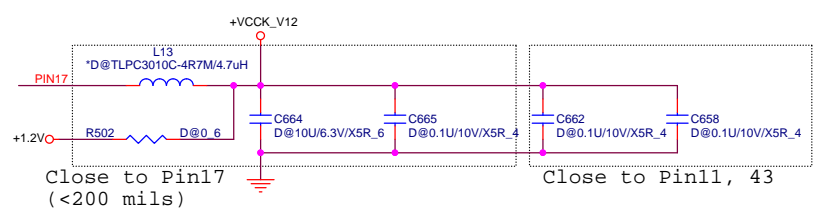
1.Level 1 Environment-related Substances Should Never be Used.
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PROJECT : HKB

Size	Document Number	Rev
	Woofer(ALC1003-CGT)	1A
Date:	Friday, June 14, 2013	Sheet 34 of 36



		MODE_CFG0(PIN47)	
		0	1
MODE_CFG1(PIN48)	0	X	EP MODE
	1	ROM ONLY MODE	EEPROM MODE

1. Level 1 Environment-related Substances Should Never be Used.
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I/O PORT LIST

USB PORT Architecture	
PORT 0	USB2.0
PORT 1	USB2.0
PORT 2	N/A
PORT 3	N/A
PORT 4	N/A
PORT 5	Touch Screen
PORT 6	WiMAX/BT
PORT 7	Camera
PORT 8	N/A
PORT 9	N/A
PORT 10	USB3.0
PORT 11	USB3.0
PORT 12	N/A
PORT 13	N/A

PCIE BUS	
PORT 0	WLAN Port
PORT 1	CARD READER
PORT 2	GLAN(RTL8111GS)
PORT 3	N/A

SATA BUS	
PORT 0	HDD
PORT 1	ODD
PORT 2	N/A
PORT 3	N/A
PORT 4	N/A
PORT 5	N/A

M/B ID LIST

SIZE	Board ID0
HKA 14"	0
HKB 15"	1

I/F	Board ID1
eDP	0
LVDS	1

CPU	Board ID2	Board ID3
A4	0	0
A6	0	1
A8	1	0
A10	1	1

SM BUS LIST

SM BUS	MBCLK/MBDATA	WRITE	READ	Function
ISL88732HRTZ-T	0001 001X	0001 0010	0001 0011	Charger

SM BUS	MBCLK_BAT/MBDATA_BAT	WRITE	READ	Function
VGP-BPS35A	0001 011X	0001 0110	0001 0111	Battery

SM BUS	SMB0_RUN_CLK/SMB0_RUN_DAT	WRITE	READ	Function
DIMM Module 0	1010 000X	1010 0000	1010 0001	DDRIII
DIMM Module 1	1010 010X	1010 0100	1010 0101	DDRIII

SM BUS	SMB1_RUN_CLK/SMB1_RUN_DAT	WRITE	READ	Function
Synaptics	0010 110X	0010 1100	0010 1101	Click PAD

POWER MAP

	S0	S3	S4	S5 (Charger Enable)	S5 (Charger Disable)
RUN_ON_CPU	H	L	L	L	L
+NB_CORE	H	L	L	L	L
+VCC_CORE	H	L	L	L	L
+1.2V	H	L	L	L	L
RUN_ON	H	L	L	L	L
+5V	H	L	L	L	L
+3V	H	L	L	L	L
+2.5V	H	L	L	L	L
+1.1V_RUN	H	L	L	L	L
+0.75V_DDR_VTT	H	L	L	L	L
SUS_ON	H	H	L	L	L
+1.35V_SUS	H	H	L	L	L
+3V_SUS	H	H	L	L	L
+1.1V_SUS	H	H	L	L	L
S5_ON_1.1V	H	H	*H/L	L	L
+1.1V_S5	H	H	*H/L	L	L
S5_ON_3V	H	H	*H/L	L	L
+3V_S5	H	H	*H/L	L	L
EC_WAKE_ON	H	H	*H/L	H	L
+3V_WAKE	H	H	*H/L	H	L
+5V_WAKE	H	H	*H/L	H	L
RUN_ON_5V	H	L	L	L	L
+5V_ODDHDD	H	L	L	L	L

* H: If wake up event exists.